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ARCHITECT INTELLIGENCE

제품 가이드 2025

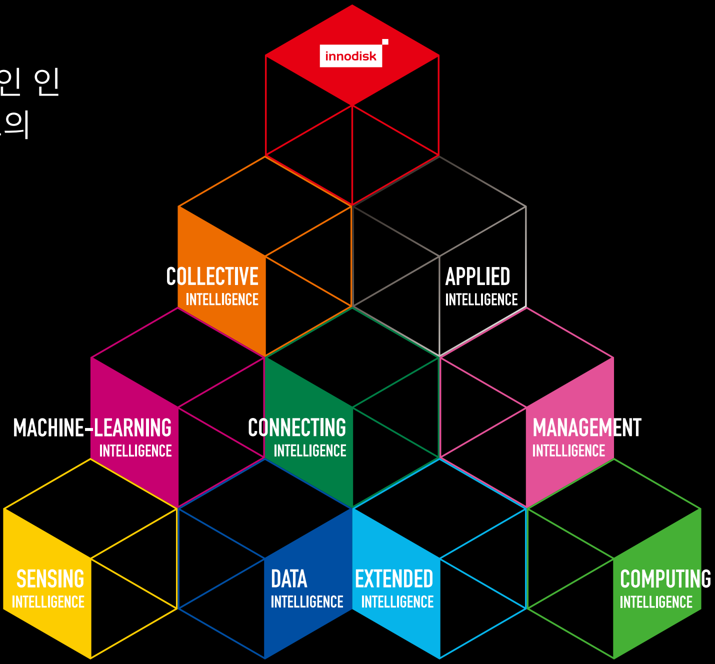
목차

INNODISK:
인텔리전스 아키텍트

이노디스크는 지능형 산업 솔루션의 글로벌 리더로, 업계 최고의 구성 요소와 AI 컴퓨팅 플랫폼의 원활한 통합을 개척하고 있습니다. 인텔리전스의 설계자로서 우리는 깊은 전문 지식과 전략적인 전 세계 파트너십을 활용하여 산업 및 기업 애플리케이션을 혁신하는 다재다능한 솔루션을 개발하고 있습니다.

설립 2005 년 대만에 설립 및 본사를 둔 저희는 2025 년 창립 20 주년을 자랑스럽게 맞이합니다. 20 개 글로벌 지점의 엔지니어링 전문가 및 영업팀과 함께 타의 추종을 불허하는 서비스 품질과 신뢰성을 제공하며 다양한 시장에서 실제 시나리오에서 AI 솔루션을 성공적으로 구현하고 있습니다.

유연한 협업 방식은
소프트웨어, 하드웨어, 펌웨어 기술을 포괄적인 인텔리전스 빌딩 블록에 통합하여 각 클라이언트의 고유한 요구 사항을 정확하게 충족하는 맞춤형 솔루션을 보장합니다. 이러한 총체적인 접근 방식을 통해 우리는 산업 인텔리전스의 미래를 지속적으로 설계하여 가능성을 현실로 전환합니다.



LEARN MORE

산업계
전반에 걸친 솔루션

당사는 업계 인사이트와 가시적인 성과 사이의 간극을 메우고 있습니다.

제조

AI 솔루션은 정확하고 즉각적인 의사 결정으로 효율성, 안전성 및 공장 생산량을 향상시킵니다.

- 자율 이동 로봇(AMR)
- 자동 광학 검사(AOI)
- 스마트 팩토리

통신

당사의 솔루션은 과부하 상황에서 중요한 통신 인프라에 대해 높은 안정적인 성능을 보장합니다.

- 5G 기지국
- 레코딩 및 방송 시스템

교통

당사의 솔루션은 EV(전기차), 버스, 지하철 등의 작동, 관리 및 보안을 강화합니다.

- EV 충전
- 자율주행 차량

헬스케어

첨단 솔루션으로 헬스케어 분야에 AI를 통합하여 엄격한 의료 수요를 충족하고 있습니다.

- 스마트 간호 시스템
- 포장 및 검사

감시 및 안전

당사의 솔루션은 최신 보안 감시 요구에 맞는 고급 분석 및 즉각적 대응을 제공합니다.

- 스마트 가로등
- PPE 감지

엔터테인먼트

디바이스 수명을 연장하고 데이터를 보호하며 엔터테인먼트 기준을 충족하는 솔루션을 제공합니다.

- 카지노

데이터센터

증가하는 데이터 문제에 대처하고 제품 수명을 연장하며 서버와 데이터센터의 전력을 절감합니다.

- 클라우드 스토리지 시스템
- 엣지 컴퓨팅 서버
- AI 트레이닝 서버

항공우주

당사는 항공우주 산업의 고유 난제에 맞춰진 최첨단 솔루션을 개발합니다.

- 미션 크리티컬
- 러기드 시스템

소매 및 물류

효율성과 보안을 강화하여 쇼핑, 주문, 배송을 개선하는 스마트 리테일을 주도합니다.

- 스마트 자동판매기
- 셀프 체크아웃 시스템

기술 및 혁신

이노디스크는 신뢰성, 내구성, 성능에 중점을 둔 산업용 기술을 개발합니다. 포괄적인 하드웨어, 펌웨어 및 소프트웨어 통합을 통해 까다로운 환경에서도 작동하도록 설계된 지능형 솔루션을 제공합니다. 당사의 맞춤화 기능을 통해 각 솔루션이 산업용 애플리케이션 요구 사항을 정확하게 충족하도록 보장합니다.

데이터 최적화

iDATA GUARD

효율적인 전력 순환과 데이터 무결성을 보장합니다.

iPOWER GUARD

SSD를 보호하고 전원 불안정성을 방지합니다.

iRETENTION

지능형 알고리즘을 활용하여 온도 및 P/E 사이클 데이터를 모니터링합니다.

엔드투엔드 데이터 경로 보호 (ETEP)

모든 단계에서 데이터 무결성을 보장합니다.

보안

PLP (iCELL)

SSD가 미션 크리티컬 데이터를 확실하게 보호하고 데이터 손실을 확실하게 방지합니다.

AES

AES 암호화는 기밀 데이터를 보호합니다.

쓰기 방지

플래시 스토리지에 저장된 데이터를 안전하게 보호합니다.

데이터 최적화

광범위한 온도

-40° C ~ 85° C 의 작동 온도를 지원합니다.

황산화 방지

극심한 환경에서도 유황 부식에 강한 면을 보입니다.

컨포멀 코팅

산, 먼지 및 기타 유해 물질로부터 DRAM PCB를 보호합니다.

러기드 클립

모듈 안정성과 고충격 강도를 강화합니다.

히트 스프레더

과열을 방지하고 제품 수명을 연장합니다.

사이드 필

칩과 보드 사이의 연결을 강화합니다.

수명

iSLC / 울트라 iSLC

디바이스의 수명을 연장하고 전반적인 성능을 향상시킵니다.

웨어 레벨링

디바이스 수명 전반에 걸쳐 블록을 고르게 사용할 수 있도록 보장합니다.

가비지 컬렉션 및 TRIM

불필요한 데이터를 제거하고 스토리지의 수명을 연장합니다.

복구

InnoOSR

InnoOSR의 특허받은 펌웨어 기술 덕분에 클릭 한 번으로 복구가 가능합니다.

클라우드 복구

운영자가 클라우드를 통해 원격으로 디바이스를 복구할 수 있습니다.

로컬 복구

현장 디바이스 복구를 지원합니다.

innodisk

APPLIED INTELLIGENCE

모든 시나리오에 준비된모듈형 솔루션

당사의 지능형 솔루션은 고객의 특정 요구에 맞춰 유연성과 사용자 맞춤 기능을 제공하도록 설계되었습니다 . 실제 응용 사례를 살펴보고 인사이트와 영감을 얻어 자신만의 성공 스토리를 만듭니다 .

최적화된 AI 시스템

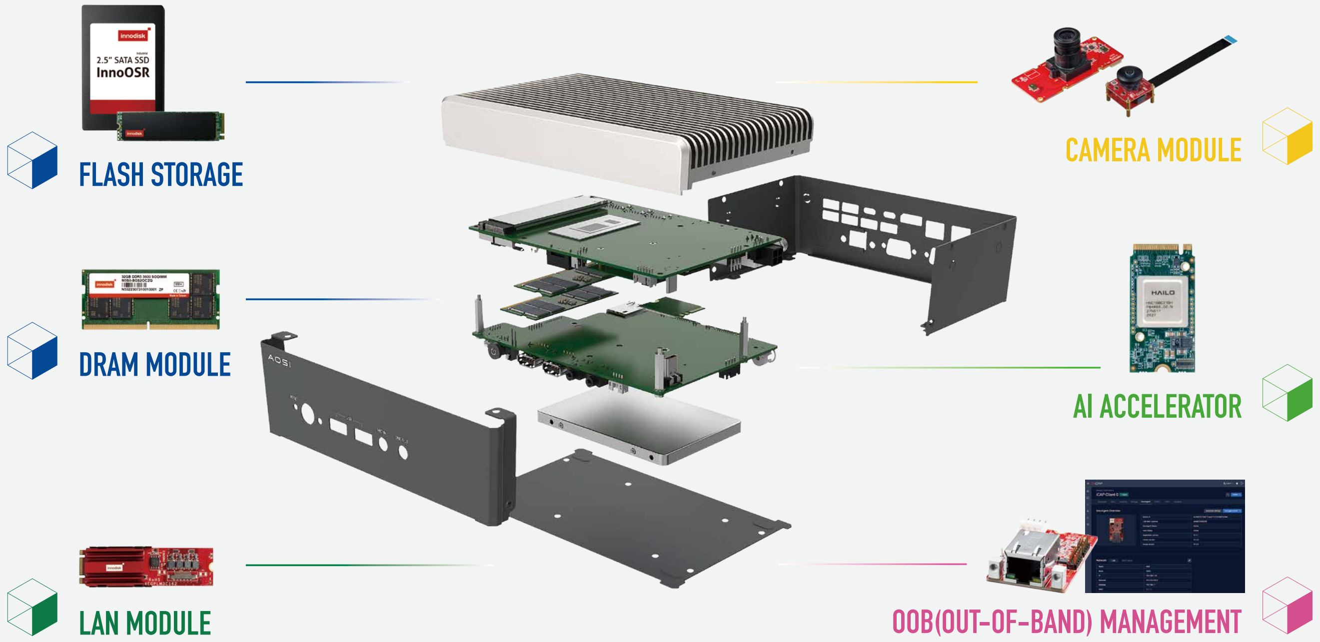
엣지 AI 학습 및 추론을 위한 최적화된 AI 시스템 .

애플리케이션 시나리오

실제 애플리케이션과 시나리오를 위한 통합 솔루션 .

최적화된 AI 시스템

지능형 빌딩 블록을 활용하여, 당사의 최적화된 시스템은 컴포넌트에서 컴퓨팅 플랫폼, 소프트웨어에서 펌웨어 기술에 이르기까지 다양한 요소를 결합합니다.



AI를 핵심으로 하는 최적화된 시스템은 다양한 AI 가속기 옵션을 제공하며, 고객의 고유한 요구에 맞는 즉시 사용할 수 있는 솔루션을 개발할 수 있도록 맞춤화할 수 있습니다.

맞춤형 AI 솔루션

최적화된 계산 성능

원활한 하드웨어 호환성

부가가치 제공 및 전문 지원

APEX-X100

NVIDIA GPU x Intel Solution

Intel-Based AI System with NVIDIA RTX 6000 Ada Accelerator

- Supports 18,176 CUDA Cores, 568 Tensor Cores, and 142 RT Cores with 48GB GDDR6 memory for AI LLM/SLM applications.
- Intel 13th Gen Core i7/i9 CPU, with up to 128GB DDR5 DRAM and 1TB NVMe SSD pre-installed.

Platform	Intel CPU	Core i9-13900E	Core i7-13700E
	Cores (P+E+LPE)	24C (8P + 16E)	16C (8P + 8E)
	Max. Frequency	5.2GHz	5.1GHz
AI Accelerator	AI Engine	NVIDIA RTX 6000 Ada	
	Form Factor (Interface)	11.2cm H x 26.7cm L, dual slot, full height (PCIe Gen 4 x16)	
	Cores	18,176 x NVIDIA Ada Lovelace architecture-based CUDA Cores 568 x NVIDIA fourth-generation Tensor Cores 142 x NVIDIA third-generation RT Cores	
	GPU memory	48GB GDDR6 (w/ECC)	
Memory	Technology / Socket	DDR5 4400MHz[*1] / 4 x 288pin DDR5 U-DIMM	
	Max. Capacity	up to 128GB (4 x 32GB, total 128GB pre-installed)	up to 128GB (2 x 32GB, total 64GB pre-installed)
Displays	HDMI 2.0 (4K@30Hz)	1	
	DP++ 1.4 (4K@60Hz)	2	
	VGA	1 (optional, share the same connector with GPIO/DIO)	
Ethernet	LAN (Marvell AQC113 10Gbps)	1	
	LAN (Intel I226 2.5Gbps)	3 x (LAN2/3 support 802.at with 30W PoE)	
Expansion Slots	M.2 2280 M Key	1 x (PCIe Gen 4 x4),1TB M.2 SSD pre-installed	1 x (PCIe Gen 4 x4), 512GB M.2 SSD pre-installed
	M.2 2230 E Key	1 x (PCIe Gen 3 x1/USB 2.0)	
	M.2 3052 B Key	1 x (USB 3.2), with Nano SIM socket	
	PCIe x16	2 x (Gen 4*2 x16 signal), RTX 6000 Ada pre-installed or 2 x (Gen4[*2] x8 signal)	
	PCIe x16	1 x (Gen 3 x4 signal)	
	PCIe x4	1 x (Gen 3 x4 signal)	
	PCIe x1	1 x (Gen 3 x1 signal)	
External I/O	COM1	RS232/422/485	
	COM2	RS232/422/485	
	COM3	RS485 (RJ45)	
	USB 3.2 Gen 2x2 (20Gbps) Type C	1	
	USB 3.2 Gen 2 (10Gbps)	8	
	Buttons	1 x Power	
	Audio (Realtek ALC888S)	Mic-in x 1, Line-out x 1	
	GPIO/DIO	8-bit (4 in/ 4 out)	
Power	Power Input Voltage	DC 24~48V	
	Power Consumption	24V@25A (with i9-13900E/ 1TB SSD/ 128GB DRAM/ NVIDIA RTX6000 Ada)	
Environment	Operating Temperature	0°C~40°C (with NVIDIA RTX 6000 Ada)	
Miscellaneous	LED Indicator	2 x Power LED, 2 x Fan LED, 2 x Temp LED	
Physical Characteristics	Dimension L x W x H (mm)	340 x 279 x 215	
	Net Weight / Gross Weight (KG)	11 / 17	
	Mount	Wall Mount / Desk mount	
	Antenna Holes	6	
Regulation	Safety	CE/FCC/UKCA	

[*1] by Intel CPU limitation [*2] by PCIe ReDriver IC limitation

APEX-P100

NVIDIA GPU x Intel Solution

Intel-Based AI System with NVIDIA RTX 5000 Ada Accelerator

- Supports 9,728 CUDA Cores, 304 Tensor Cores, and 76 RT Cores with 16GB GDDR6 memory for factory AOI and AI medical imaging recognition.
- Intel 13th Gen Core i7 CPU, 32GB DDR5 DRAM and 512GB NVMe SSD are pre-installed.

Platform	Intel CPU	Core i7-13700E
	Cores (P+E+LPE)	16C (8P + 8E)
	Max. Frequency	5.1GHz
AI Accelerator	AI Engine	NVIDIA RTX 5000 Ada
	Form Factor (Interface)	MXM graphics module version 3.1, Type B (PCIe Gen 4 x 16)
	Cores	9,728 x NVIDIA Ada Lovelace architecture-based CUDA Cores 304 x NVIDIA fourth-generation Tensor Cores 76 x NVIDIA third-generation RT Cores
	GPU memory	16GB GDDR6 (w/ECC)
Memory	Technology / Socket	DDR5 5200MHz / 2 x 262pin DDR5 SO-DIMM
	Max. Capacity	up to 64GB (2 x 16GB, total 32GB pre-installed)
Displays	DP++ 1.4 (4K@60Hz)	5
Ethernet	LAN (Intel I226 2.5Gbps)	5
Expansion Slots	M.2 2280 M Key	2 x (PCIe Gen 4 x4 / SATAIII), 512GB M.2 SSD pre-installed
	MXM Type B / B+	1 x (PCIe Gen4 x16), NVIDIA RTX 5000 Ada pre-installed
External I/O	COM1	RS232/422/485
	COM2	RS232/422/485
	COM3	RS232/422/485
	COM4	RS232/422/485
	USB 3.2 Gen 2x2 (20Gbps) Type C	1
	USB 3.2 Gen 2 (10Gbps)	6
	USB 2.0	2
	Buttons	1 x Power (with LED)
	Audio (Realtek ALC888S)	Mic-in x 1, Line-out x 1
	GPIO/ DIO	7-bit (by BIOS selection)
Power	Power Input Voltage	DC 24V
	Power Consumption	24V@19.8A (with i7-13700E/ 512GB SSD/ 32GB DRAM/ NVIDIA RTX 5000 Ada)
Environment	Operating Temperature	0°C~50°C (with NVIDIA RTX 5000 Ada)
Physical Characteristics	Dimension L x W x H (mm)	280 x 270 x 148.2
	Net Weight / Gross Weight (KG)	5.7 / 8
	Mount	Wall Mount
Regulation	Safety	CE/FCC

APEX-P200

NVIDIA GPU x Intel Solution

Intel-Based AI System with NVIDIA RTX 2000 Ada Accelerator

- Supports 3,072 CUDA Cores, 96 Tensor Cores, and 24 RT Cores with 8GB GDDR6 memory for AI medical imaging diagnostics and object detection.
- Intel 13th Gen Core i7 CPU, 32GB DDR5 DRAM and 512GB NVMe SSD are pre-installed.
- Compact design with dimensions of 182mm x 158.6mm x 90mm for efficient space usage.

Platform	Intel CPU	Core i7-13800HE
	Cores (P+E+LPE)	14C (6P + 8E)
	Max. Frequency	5GHz
AI Accelerator	AI Engine	NVIDIA RTX 2000 Ada
	Form Factor (Interface)	MXM graphics module version 3.1, Type A (PCIe Gen 4 x 8)
	Cores	3,072 x NVIDIA Ada Lovelace architecture-based CUDA Cores 96 x NVIDIA fourth-generation Tensor Cores 24 x NVIDIA third-generation RT Cores
	GPU memory	8GB GDDR6 (w/ECC)
Memory	Technology / Socket	DDR5 5200MHz / 2 x 262pin DDR5 SO-DIMM
	Max. Capacity	up to 64GB (2 x 16GB, total 32GB pre-installed)
Displays	HDMI 2.1 (8K@60Hz)	1
Ethernet	LAN (Intel I226 2.5Gbps)	3x (LAN 2/3 support 802.at with 30W PoE)
Expansion Slots	M.2 2280 M Key	1 x (PCIe Gen 4 x4),512GB M.2 SSD pre-installed
	M.2 2230 E Key	1 x (PCIe Gen 3 x1/USB 2.0)
	MXM Type A	1 x (PCIe Gen 4 x8), RTX 2000 Ada pre-installed
External I/O	COM1	RS232/422/485 (5V/12V)
	COM2	RS232/422/485
	USB 3.2 Gen 2 (10Gbps)	2
	USB 2.0	2
	Buttons	1 x Power (with LED)
	Audio (Realtek ALC888S)	Mic-in x 1, Line-out x 1
Power	Power Input Voltage	DC 19V
	Power Consumption	19V@10.5A (with i7-13800HE/ 512GB SSD/ 32GB DRAM/ NVIDIA RTX 2000 Ada)
Environment	Operating Temperature	-20°C~60°C
Miscellaneous	LED Indicator	1 x HDD LED
Physical Characteristics	Dimension L x W x H (mm)	182 x 158.6 x 90
	Net Weight / Gross Weight (KG)	3 / 3.7
	Mount	Wall Mount
	Antenna Holes	2
Regulation	Safety	CE/FCC/UKCA

APEX-E100

Intel x AI solution

Intel AI Box PC with Integrated NPU

- Equipped with a built-in NPU delivering up to 36 TOPS, with GPU and CPU support for AMR/AGV, AI surveillance, and visual inspection.
- Intel Core Ultra CPU, 16GB DDR5 DRAM, and 512GB NVMe SSD are pre-installed
- Supports Innodisk dual MIPI over Type-C cameras.

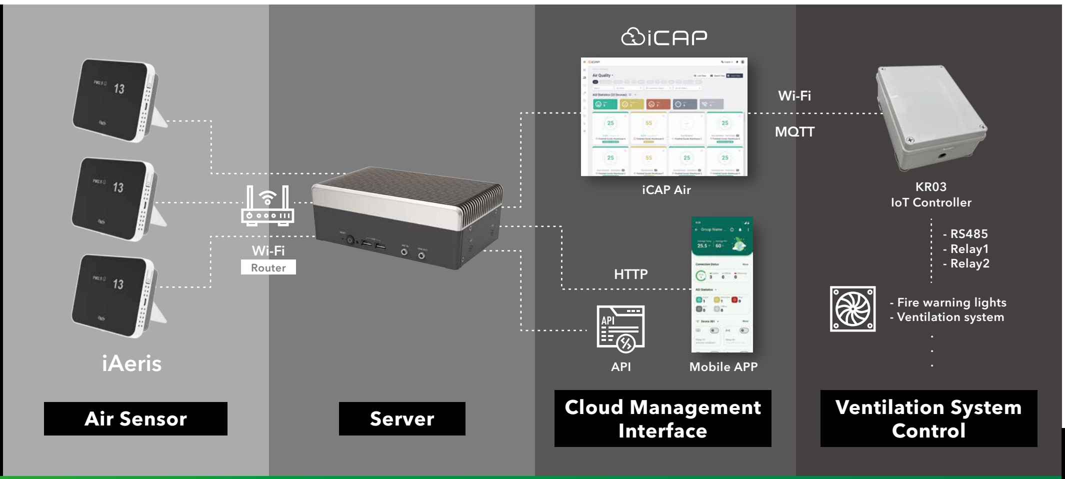
Platform	Intel CPU	Core Ultra 7 165HL	Core Ultra 5 135HL	Core Ultra 3 105UL
	Cores (P+E+LPE)	16C (6P + 8E + 2LPE)	14C (4P + 8E + 2LPE)	8C (2P + 4E + 2LPE)
	Max. Frequency	5.0GHz	4.6GHz	4.2GHz
AI Accelerator	AI Engine	Intel AI Boost up to 36 TOPS via (CPU+GPU+NPU)		
Memory	Technology / Socket	DDR5 5600MHz / 2 x 262pin DDR5 SO-DIMM		
	Max. Capacity	up to 96GB (2 x 8GB, total 16GB pre-installed)		
Displays	HDMI 2.1 (8K@30Hz)	2		
Ethernet	LAN (Intel I226 2.5Gbps)	2		
Expansion Slots	M.2 2230 E Key	1 x (PCIe Gen 3 x1 / USB 2.0)		
	M.2 2280 M Key	1 x (PCIe Gen 4 x4 / SATAIII); 512GB M.2 SSD pre-installed		
External I/O	COM1	RS232/422/485		
	USB 3.2 Gen2 (10Gbps)	2		
	USB 3.2 Gen1 (5Gbps)	2		
	USB 2.0	2		
	Buttons	1 x Power		
	Audio (Realtek ALC888S)	Mic-in x 1, Line-out x 1		
	MIPI over Type-C	2		
Power	Power Input Voltage	DC 12V		
	Power Consumption	12V@12.5A (with Ultra 7 165HL/ 1T SSD/ 32GB DRAM)		
Environment	Operating Temperature	-20°C~60°C		
Miscellaneous	LED Indicator	1 x Power LED		
Physical Characteristics	Dimension L x W x H (mm)	188 x 140 x 56		
	Net Weight / Gross Weight (KG)	1.6 / 2.1		
	Mount	Wall Mount		
	Antenna Holes	2		
Regulation	Safety	CE/FCC		

애플리케이션 시나리오

iCAP AIR

공기 품질 관리 솔루션

포괄적이고 지능적인 공기 품질 관리 솔루션



높은 감도

SHS, FCC, CE, RoHS, NCC, BSMI 및 기타 국제 인증을 획득.

그룹 관리

다양한 장소와 기기에 대해 분류하여 관리를 수행.

맞춤형 평면도

평면도를 업로드하여 다양한 장소의 기기를 관리

임계값 및 알림

다양한 공기 요인에 대한 임계값을 설정하고 즉각적인 알림을 발송.

자동 트리거

실시간 공기 질에 따라 환기 장비를 작동시키거나 일정에 따라 트리거 설정.

Air Sensor

iCAP Air Specification Table

Air Sensor Model	Temperature	Humidity	PM2.5	PM10	CO2	TVOC	HCHO*	NO2*	O3*	SO2*	CO*	NH3*	H2S*
iAeris74	●	●	●		●		Customizable						
iAeris76	●	●	●	●	●	●							

iAeris

Air Sensor

Operating Environment	-10°C ~ 50°C, below 90% RH
Storage Temperature	-20°C ~ 70°C, below 90% RH
Screen	2.23" OLED
Control interface	modbus-RTU or DO (Dry Contact)
Communication Protocol	RS485 (Modbus-RTU) / Wi-Fi (Modbus-TCP, HTTP, MQTT) (Optional) / BLE4.0(Optional)
Power Supply	DC 5V/1.0A or DC12-24V/0.5A
Power Consumption	Max 5W
Safety Standards	CE / FCC / NCC / BSMI
Dimension	114mm(L) x 96mm(W) x 36mm(H)
Weight	142g

ABOX-5120

Air Quality Server

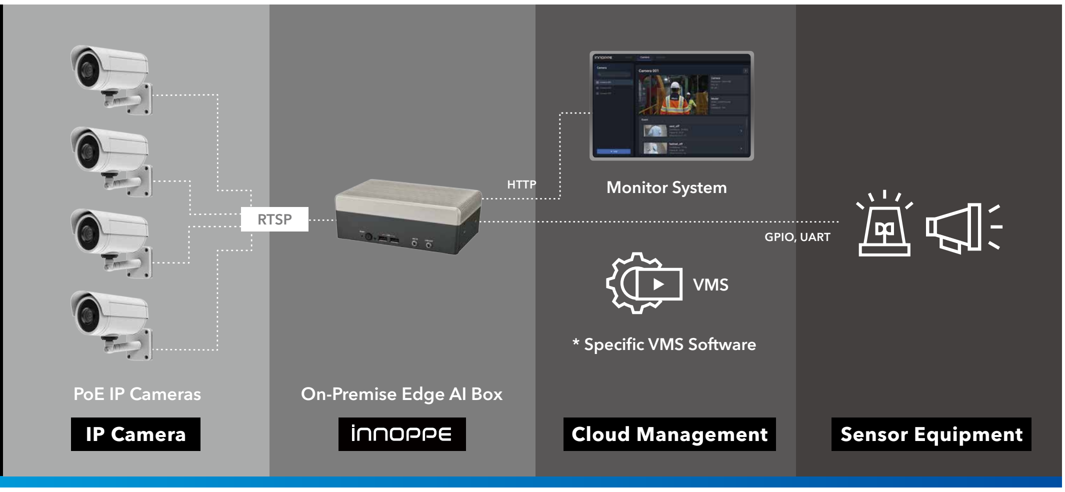
CPU	Intel® Celeron® Processor 7305E
Memory	32GB - DDR5 4800MT/s
Storage	512GB
OS	Linux / Ubuntu 22.04.3 LTS
Operating Temperature	-20°C ~ 60°C
Storage Temperature	-40°C ~ 85°C
Operating Humidity	Relative humidity: 5% to 95%, non-condensing
Vibration During Operation	With SSD: 3G, IEC 60068-2-64, random, 5~500Hz, 1hr/axis
Shock During Operation	With SSD: 30G, IEC 60068-2-27, half sine, 11ms duration
Dimension	182.17mm x 108.64mm x 63.16mm

*The air quality server is bundled with iCAP Air and is not available for separate purchase.

InnoPPE 개인 보호 장비 (PPE) 인식 솔루션

높은 유연성과 지능적인 솔루션

엣지 AI 호스트를 중심으로 프론트엔드 IP 카메라와 백엔드 관리 플랫폼이 원활하게 연결되어 AI PPE 인식 솔루션을 쉽게 구현할 수 있습니다.



* Video Management System (VMS) software is not included with InnoPPE. The diagram illustrates InnoPPE's capability to send detection events to compatible VMS platforms for alert notifications.

유연한 아키텍처

기존 IP 카메라를 활용하여 PPE를 정확하게 감지.

효율적인 배포

독립형 엣지 AI 호스트가 여러 IP 카메라를 지원하여 설치 비용을 절감.

실시간 이벤트 알림

실시간으로 위반 사항을 기록하고, 현장 경고 시스템과 연동하여 즉각적인 알림 제공.

스마트 펜스 경고

구역 감지 기능을 제공하여 무단 침입이나 배회에 대한 실시간 알림 제공.

높은 유연성의 ODM 서비스

실제 애플리케이션 환경에 맞춘 독점 맞춤형 AI 모델을 제공하여 최적의 AI 인식 성능을 보장합니다.

서드파티 소프트웨어 통합

이벤트 알림 수신 및 주요 비디오 세그먼트 녹화를 위해 Nx Witness VMS가 통합되어 있습니다.

InnoPPE 하드웨어 / 소프트웨어 사양

HARDWARE

CPU	i5-1245UE
AI Accelerator	Hailo-8
Memory	16GB DDR5 SO-DIMM
Storage	512GB
Power Requirement	9~36V DC Power supply
Temperature	Operation: -20°C ~ 60°C (Ta)
	Storage: -40°C ~ 85°C (Ta)
Certification	CE/FCC class A
Dimension (L x W x H)	182.17mm x 108.64mm x 63.16mm
Regulation	CE/FCC Class B/RoHS/UKCA
Warranty	1 Year

SOFTWARE

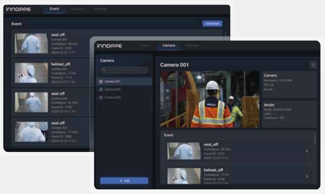
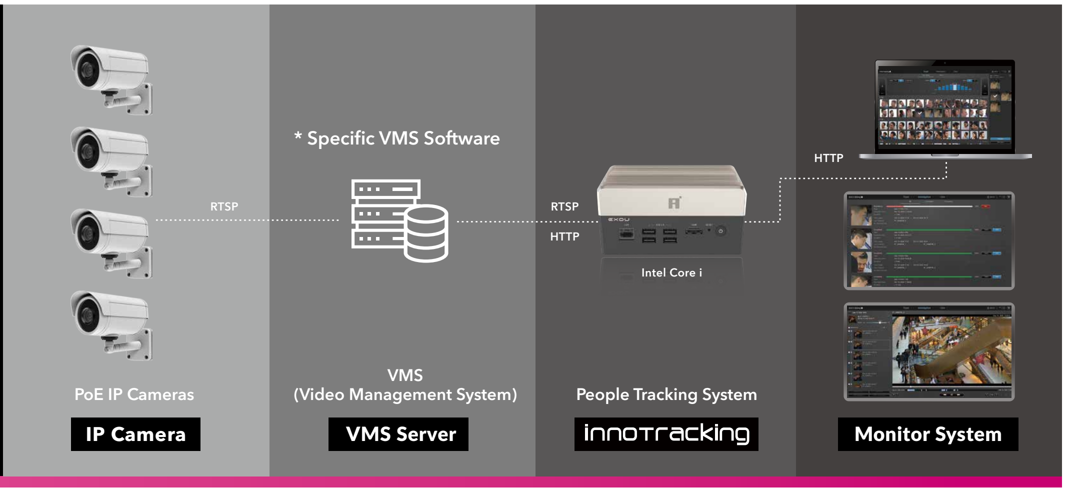


Image Sources	Supports RTSP-compatible network cameras / VMS / DVR / NVR systems
Video Format	H.264
Image Resolution	1080P / 720P / 640P
Recognition Objects	Human / Hard Helmet / Reflective Vest
FPS per Channel	5~10 fps (Varies based on channel numbers or resolution)
Support Max. Channel Number	4
Data Output Type	.csv / .db / .html
Support Browser	Chrome / Firefox / Edge
Smart Fence	Supports multiple polygonal ROIs
Web API	MQTT Protocol
OS Support	Linux (Kernel 5.15 and later)

* Customized adjustment services for related hardware and software are also available.

InnoTracking 사람 추적 솔루션

솔루션 한 눈에 보기



* InnoTracking requires receiving video streams from a specific VMS (Video Management System) software as the video source. InnoTracking does not include the VMS software.

정확한 AI
얼굴 비교 및 검색

사전
등록 불필요

용의자를
추적하는 쉬운 방법

기존 현장
카메라 활용

에너지
절약 및 비용 절감

견고한 설계:
고온 및 진동에 강한
산업용 PC

InnoTracking 하드웨어 사양

ABOX-5120
Edge Server

CPU	Intel® Celeron® Processor 7305E
Memory	32GB - DDR5 4800MT/s
Storage	512GB
Display	1 x USB 3.2 Gen1 Type C 1 x mini DP 1 x HDMI
Power	Input: Single 9 ~ 36 V Power Consumption: Max. 90W
OS	Linux / Ubuntu 22.04.3 LTS
Operating Temperature	-20°C ~ 60°C
Storage Temperature	-40°C ~ 85°C
Operating Humidity	5% to 95% Relative humidity, non-condensing
Vibration During Operation	With SSD: 3G, IEC 60068-2-64, random, 5~500Hz, 1hr/axis
Shock During Operation	With SSD: 30G, IEC 60068-2-27, half sine, 11ms duration
Dimension	182.17 x 108.64 x 63.16/mm
Others	Support InnoAgent out-of-band remote management (Optional)

* This edge server is bundled with the InnoTracking solution and is not available for separate purchase.

innodisk

DATA INTELLIGENCE

DATA INTELLIGENCE

강력하고 안정적인 메모리 및 스토리지 솔루션 . 당사의 산업 등급 제품은 고성능 컴퓨팅과 안전한 데이터 스토리지를 지원하도록 설계되었습니다 .

DRAM MODULE PRODUCT LINE

IC 등급 IC 계층

오리지널 IC	**오리지널 IC (Innodisk)**	- 주요 IC 공급업체에서 완전 테스트 완료
eTT	**효과적으로 테스트된 DRAM**	- 효과적으로 테스트되었으나 테스트 패턴은 공급업체마다 다를 수 있음 - 로고는 표시되지 않으며 일련번호 또는 제조사 정보만 표시됩니다
uTT	**테스트되지 않은 DRAM**	- 완전한 테스트를 통과하지 못했습니다 - 로고는 표시되지 않으며 일련번호 또는 제조사 정보만 표시됩니다
다운그레이드	**다운그레이드**	- DRAM IC 는 낮은 수율의 웨이퍼와 다이로 제작되었으며 , 심각한 호환성 및 기능 문제를 가지고 있습니다

부가가치 기능

▲: 사용 가능

		Wide Temperature	Anti-sulfuration	30μ"Gold Finger	Mounting Hole	Connector	iRAM	iSMART / iCAP	Conformal Coating	Side Fill
CXL Memory Module										
DDR5	MRDIMM		●	●				▲	▲	▲
	LPDDR5X CAMM2		●					▲	▲	▲
	CAMM2		●					▲	▲	▲
	CUDIMM	●	●	●				▲	▲	▲
	CSODIMM	●	●	●				▲	▲	▲
	UDIMM	●	●	●				▲	▲	▲
	SODIMM	●	●	●				▲	▲	▲
	ECC UDIMM	●	●	●				▲	▲	▲
	ECC SODIMM	●	●	●				▲	▲	▲
	RDIMM	●	●	●				▲	▲	▲
	UDIMM ULP	●	●	●				▲	▲	▲
	ECC UDIMM VLP	●	●	●				▲	▲	▲
	RDIMM VLP	●	●	●				▲	▲	▲
	UDIMM Ultra Temperature	●	●	● (45μ")				▲	▲	●
	SODIMM Ultra Temperature	●	●	● (45μ")				▲	▲	●
DDR4	UDIMM	●	●					▲	▲	▲
	SODIMM	●	●					▲	▲	▲
	ECC UDIMM	●	●	●			●	▲	▲	▲
	ECC SODIMM	●	●	●			●	▲	▲	▲
	RDIMM	●	●	●			●	▲	▲	▲
	UDIMM VLP	●	●					▲	▲	▲
	SODIMM VLP		●					▲	▲	▲
	ECC UDIMM VLP	●	●	●			●	▲	▲	▲
	ECC SODIMM VLP	●	●	●			●	▲	▲	▲
	Mini ECC VLP		●	●			●	▲	▲	▲
	RDIMM VLP	●	●	●			●	▲	▲	▲
	Mini RDIMM VLP		●	●			●	▲	▲	▲
	XR-DIMM		●		●	●	●	▲	▲	▲
	Rugged DIMM	●	●		●			▲	▲	▲
	SODIMM Ultra Temperature	●	●	● (45μ")				▲	▲	●
	ECC SODIMM Ultra Temperature	●	●	● (45μ")				▲	▲	●
DDR3	UDIMM	●						▲	▲	▲
	SODIMM	●						▲	▲	▲
	ECC UDIMM	●		●			●	▲	▲	▲
	ECC SODIMM	●		●			●	▲	▲	▲
	RDIMM			●			●	▲	▲	▲
DDR2	UDIMM							▲	▲	▲
	SODIMM	●						▲	▲	▲
	ECC UDIMM			●			●	▲	▲	▲
DDR1	UDIMM							▲	▲	▲
	SODIMM							▲	▲	▲
SDRAM	SODIMM							▲	▲	▲

DRAM MODULE

CXL Memory Module

Model Name	CXL Memory Module
CXL Compliance	CXL 1.1 & CXL 2.0
CXL Protocol	Type 3 (CXL.mem & CXL.io)
Interface	PCIe Gen 5 x8
DRAM IC Generation	DDR5
Form Factor	E3.S 2T
Connector	EDSFF 2C (84 pin)
Density	64GB
Operation Temperature	0°C ~ 70°C

DDR5 DRAM Module

Module Type	DDR5 MRDIMM	LPDDR5X CAMM2	DDR5 CAMM2	DDR5 CUDIMM
Speed	8800MT/s	8533 MT/s	6400 MT/s	6400 MT/s
Density	32GB, 64GB, 96GB	32GB, 64GB	32GB, 64GB	8GB, 16GB,24GB, 32GB, 48GB, 64GB
Function	Registered Memory with ECC	Non-ECC Unbuffered Memory	Non-ECC Unbuffered Memory	Non-ECC Unbuffered Memory
Pin Number	287pin	644pin	644pin	288pin
Bus Width	x80	x128	x128	x64
Voltage	1.1V	1.05V	1.1V	1.1V
PCB Height	1.23 Inches	1.30 Inches	1.57 Inches	1.23 Inches
Operating Temperature	0°C ~ 95°C (Tc)	0°C ~ 85°C (Tc)	0°C ~ 95°C (Tc)	0°C ~ 95°C (Tc)

Module Type	DDR5 CSODIMM	DDR5 UDIMM	DDR5 SODIMM	DDR5 ECC UDIMM
Speed	6400MT/s	4800 MT/s, 5600 MT/s	4800 MT/s, 5600 MT/s	4800 MT/s, 5600 MT/s
Density	8GB, 16GB, 24GB, 32GB, 48GB, 64GB	8GB, 16GB, 24GB, 32GB, 48GB	8GB, 16GB, 24GB, 32GB, 48GB	16GB, 24GB, 32GB, 48GB
Function	Non-ECC Unbuffered Memory	Non-ECC Unbuffered Memory	Non-ECC Unbuffered Memory	ECC Unbuffered Memory
Pin Number	262pin	288pin	262pin	288pin
Bus Width	x64	x64	x64	x72
Voltage	1.1V	1.1V	1.1V	1.1V
PCB Height	1.18 Inches	1.23 Inches	1.18 Inches	1.23 Inches
Operating Temperature	0°C ~ 95°C (Tc)	0°C ~ 95°C (Tc)	0°C ~ 95°C (Tc)	0°C ~ 95°C (Tc)

Module Type	DDR5 ECC SODIMM	DDR5 RDIMM	DDR5 UDIMM ULP	DDR5 ECC UDIMM VLP
Speed	4800 MT/s, 5600 MT/s	4800 MT/s, 5600MT/s	4800 MT/s, 5600 MT/s	4800 MT/s, 5600 MT/s
Density	16GB, 24GB, 32GB, 48GB	16GB, 32GB, 64GB, 96GB,128GB	16GB, 32GB	16GB, 32GB
Function	ECC Unbuffered Memory	Registered Memory with ECC	Non-ECC Unbuffered Memory	ECC Unbuffered Memory
Pin Number	262pin	288pin	288pin	288pin
Bus Width	x72	x80	x64	x72
Voltage	1.1V	1.1V	1.1V	1.1V
PCB Height	1.18 Inches	1.23 Inches	0.7 Inches	0.738 Inches
Operating Temperature	0°C ~ 95°C (Tc)	0°C ~ 95°C (Tc)	0°C ~ 95°C (Tc)	0°C ~ 95°C (Tc)

Module Type	DDR5 RDIMM VLP	DDR5 UDIMM WT	DDR5 SODIMM WT	DDR5 ECC SODIMM WT
Speed	4800 MT/s, 5600 MT/s	4800 MT/s, 5600 MT/s	4800 MT/s, 5600 MT/s	4800 MT/s, 5600 MT/s
Density	16GB, 32GB	8GB, 16GB, 24GB, 32GB, 48GB	8GB, 16GB, 24GB, 32GB, 48GB	16GB, 24GB, 32GB, 48GB
Function	Registered Memory with ECC	Non-ECC Unbuffered Memory	Non-ECC Unbuffered Memory	ECC Unbuffered Memory
Pin Number	288pin	288pin	262pin	262pin
Bus Width	x80	x64	x64	x72
Voltage	1.1V	1.1V	1.1V	1.1V
PCB Height	0.738 Inches	1.23 Inches	1.18 Inches	1.18 Inches
Operating Temperature	0°C ~ 95°C (Tc)	-40°C ~ 95°C (Tc)	-40°C ~ 95°C (Tc)	-40°C ~ 95°C (Tc)

Module Type	DDR5 ECC UDIMM WT	DDR5 RDIMM WT	DDR5 UDIMM ULP WT	DDR5 ECC UDIMM VLP WT
Speed	4800 MT/s, 5600 MT/s	4800 MT/s, 5600MT/s	4800 MT/s, 5600MT/s	4800 MT/s, 5600 MT/s
Density	16GB, 24GB, 32GB, 48GB	16GB, 32GB, 64GB, 96GB, 128GB	16GB, 32GB	16GB, 32GB
Function	ECC Unbuffered Memory	Registered Memory with ECC	Non-ECC Unbuffered Memory	ECC Unbuffered Memory
Pin Number	288pin	288pin	288pin	288pin
Bus Width	x72	x80	x64	x72
Voltage	1.1V	1.1V	1.1V	1.1V
PCB Height	1.23 Inches	1.23 Inches	0.7 Inches	0.738 Inches
Operating Temperature	-40°C ~ 95°C (Tc)	-40°C ~ 95°C (Tc)	-40°C ~ 95°C (Tc)	-40°C ~ 95°C (Tc)

Module Type	DDR5 RDIMM VLP WT	DDR5 SODIMM Ultra Temperature	DDR5 UDIMM Ultra Temperature
Speed	4800 MT/s, 5600 MT/s	4800 MT/s, 5600 MT/s	4800 MT/s, 5600 MT/s
Density	32GB	8GB, 16GB, 32GB	16GB, 32GB
Function	Registered Memory with ECC	Non-ECC Unbuffered Memory	Non-ECC Unbuffered Memory
Pin Number	288pin	262pin	288pin
Bus Width	x80	x64	x64
Voltage	1.1V	1.1V	1.1V
PCB Height	0.738 Inches	1.18 Inches	1.23 Inches
Operating Temperature	-40°C ~ 95°C (Tc)	- 40°C ~ 105°C	- 40°C ~ 105°C

DDR4 DRAM Module

Module Type	DDR4 UDIMM	DDR4 SODIMM	DDR4 ECC UDIMM	DDR4 ECC SODIMM
Speed	2133 MT/s, 2400 MT/s, 2666 MT/s, 2933 MT/s, 3200 MT/s	2133 MT/s, 2400 MT/s, 2666 MT/s, 2933 MT/s, 3200 MT/s	2133 MT/s, 2400 MT/s, 2666 MT/s, 2933 MT/s, 3200 MT/s	2133 MT/s, 2400 MT/s, 2666 MT/s, 2933 MT/s, 3200 MT/s
Density	4GB, 8GB, 16GB, 32GB	2GB, 4GB, 8GB, 16GB, 32GB	4GB, 8GB, 16GB, 32GB	2GB, 4GB, 8GB, 16GB, 32GB
Function	Non-ECC Unbuffered Memory	Non-ECC Unbuffered Memory	ECC Unbuffered Memory	ECC Unbuffered Memory
Pin Number	288pin	260pin	288pin	260pin
Bus Width	x64	x64	x72	x72
Voltage	1.2V	1.2V	1.2V	1.2V
PCB Height	1.23 Inches	1.18 Inches	1.23 Inches	1.18 Inches
Operating Temperature	0°C ~ 95°C (Tc)	0°C ~ 95°C (Tc)	0°C ~ 95°C (Tc)	0°C ~ 95°C (Tc)

Module Type	DDR4 RDIMM	DDR4 UDIMM VLP	DDR4 SODIMM VLP	DDR4 ECC UDIMM VLP
Speed	2133 MT/s, 2400 MT/s, 2666 MT/s, 2933 MT/s, 3200 MT/s	2133 MT/s, 2400 MT/s, 2666 MT/s	2133 MT/s, 2400 MT/s, 2666 MT/s	2133 MT/s, 2400 MT/s, 2666 MT/s, 2933 MT/s, 3200 MT/s
Density	4GB, 8GB, 16GB, 32GB, 64GB, 128GB	4GB, 8GB, 16GB	4GB, 8GB	4GB, 8GB, 16GB, 32GB
Function	Registered Memory with ECC	Non-ECC Unbuffered Memory	Non-ECC Unbuffered Memory	ECC Unbuffered Memory
Pin Number	288pin	288pin	260pin	288pin
Bus Width	x72	x64	x64	x72
Voltage	1.2V	1.2V	1.2V	1.2V
PCB Height	1.23 Inches	0.738 Inches	0.7 Inches	0.738 Inches
Operating Temperature	0°C ~ 95°C (Tc)	0°C ~ 95°C (Tc)	0°C ~ 95°C (Tc)	0°C ~ 95°C (Tc)

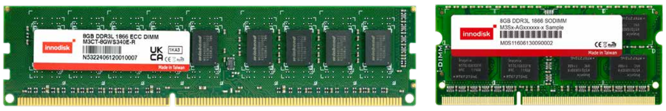
Module Type	DDR4 ECC SODIMM VLP	DDR4 Mini ECC VLP	DDR4 RDIMM VLP	DDR4 Mini RDIMM VLP
Speed	2133 MT/s, 2400 MT/s, 2666 MT/s	2133 MT/s, 2400 MT/s, 2666 MT/s	2133 MT/s, 2400 MT/s, 2666 MT/s, 2933 MT/s, 3200 MT/s	2133MT/s,2400 MT/s,2666MT/s
Density	4GB, 8GB	4GB, 8GB, 16GB, 32GB	4GB, 8GB, 16GB, 32GB	4GB, 8GB,16GB
Function	ECC Unbuffered Memory	ECC Unbuffered Memory	Registered Memory with ECC	Registered Memory with ECC
Pin Number	260pin	288pin	288pin	288pin
Bus Width	x72	x72	x72	x72
Voltage	1.2V	1.2V	1.2V	1.2V
PCB Height	0.7 Inches	0.738 Inches	0.738 Inches	0.738 Inches
Operating Temperature	0°C ~ 95°C (Tc)	0°C ~ 95°C (Tc)	0°C ~ 95°C (Tc)	0°C ~ 95°C (Tc)

Module Type	DDR4 XR-DIMM	DDR4 UDIMM WT	DDR4 SODIMM WT	DDR4 ECC UDIMM WT
Speed	2400 MT/s,2666 MT/s	2133 MT/s, 2400 MT/s, 2666 MT/s, 3200 MT/s	2133 MT/s, 2400 MT/s, 2666 MT/s, 3200 MT/s	2133 MT/s, 2400 MT/s, 2666 MT/s, 3200 MT/s
Density	8GB, 16GB	4GB, 8GB, 16GB, 32GB	4GB, 8GB, 16GB, 32GB	4GB, 8GB, 16GB, 32GB
Function	ECC Unbuffered Memory	Non-ECC Unbuffered Memory	Non-ECC Unbuffered Memory	ECC Unbuffered Memory
Pin Number	300pin	288pin	260pin	288pin
Bus Width	x72	x64	x64	x72
Voltage	1.2V	1.2V	1.2V	1.2V
PCB Height	1.18 Inches	1.23 Inches	1.18 Inches	1.23 Inches
Operating Temperature	0°C ~ 95°C (Tc)	-40°C ~ 95°C (Tc)	-40°C ~ 95°C (Tc)	-40°C ~ 95°C (Tc)

Module Type	DDR4 ECC SODIMM WT	DDR4 RDIMM WT	DDR4 UDIMM VLP WT	DDR4 ECC UDIMM VLP
Speed	2133 MT/s, 2400 MT/s, 2666 MT/s, 3200 MT/s	2133 MT/s, 2400 MT/s, 2666 MT/s, 3200 MT/s	2400 MT/s	2133 MT/s, 2400 MT/s, 2666 MT/s, 2933 MT/s, 3200 MT/s
Density	4GB, 8GB, 16GB, 32GB	4GB, 8GB, 16GB, 32GB, 64GB, 128GB	8GB, 16GB	8GB, 16GB, 32GB
Function	ECC Unbuffered Memory	Registered Memory with ECC	Non-ECC Unbuffered Memory	ECC Unbuffered Memory
Pin Number	260pin	288pin	288pin	288pin
Bus Width	x72	x72	x64	x72
Voltage	1.2V	1.2V	1.2V	1.2V
PCB Height	1.18 Inches	1.23 Inches	0.738 Inches	0.738 Inches
Operating Temperature	-40°C ~ 95°C (Tc)	-40°C ~ 95°C (Tc)	-40°C ~ 95°C (Tc)	-40°C ~ 95°C (Tc)

Module Type	DDR4 ECC SODIMM VLP WT	DDR4 RDIMM VLP WT	DDR4 Rugged DIMM
Speed	2133 MT/s, 2400 MT/s, 2666 MT/s, 3200 MT/s	2133 MT/s, 2400 MT/s, 2666 MT/s, 3200 MT/s	2400 MT/s
Density	8GB	4GB, 8GB, 16GB, 32GB	16GB
Function	ECC Unbuffered Memory	Registered Memory with ECC	Non-ECC Unbuffered Memory
Pin Number	260pin	288pin	260pin
Bus Width	x72	x72	x64
Voltage	1.2V	1.2V	1.2V
PCB Height	0.7 Inches	0.738 Inches	1.18 Inches
Operating Temperature	-40°C ~ 95°C (Tc)	-40°C ~ 95°C (Tc)	-40°C ~ 95°C (Tc)

Module Type	DDR4 SODIMM Ultra Temperature	DDR4 ECC SODIMM Ultra Temperature
Speed	2133 MT/s, 2400 MT/s, 2666 MT/s, 2933 MT/s, 3200 MT/s	2133 MT/s, 2400 MT/s, 2666 MT/s, 2933 MT/s, 3200 MT/s
Density	16GB, 32GB	16GB, 32GB
Function	Non-ECC Unbuffered Memory	ECC Unbuffered Memory
Pin Number	260pin	260pin
Bus Width	x64	x72
Voltage	1.2V	1.2V
PCB Height	1.18 Inches	1.18 Inches
Operating Temperature	-40°C ~ 95°C (Tc)	-40°C ~ 95°C (Tc)



DDR3 DRAM Module

Module Type	DDR3 UDIMM	DDR3 SODIMM	DDR3 ECC UDIMM	DDR3 ECC SODIMM	DDR3 RDIMM
Speed	1066 MT/s, 1333 MT/s, 1600 MT/s, 1866 MT/s	1066 MT/s, 1333 MT/s, 1600 MT/s, 1866 MT/s	1066 MT/s, 1333 MT/s, 1600 MT/s, 1866 MT/s	1066 MT/s, 1333 MT/s, 1600 MT/s, 1866 MT/s	1333 MT/s, 1600 MT/s, 1866 MT/s
Density	2GB, 4GB, 8GB	1GB, 2GB, 4GB, 8GB	2GB, 4GB, 8GB	2GB, 4GB, 8GB	2GB, 4GB, 8GB
Function	Non-ECC Unbuffered Memory	Non-ECC Unbuffered Memory	ECC Unbuffered Memory	ECC Unbuffered Memory	Registered Memory with ECC
Pin Number	240pin	204pin	240pin	204pin	240pin
Bus Width	x64	x64	x72	x72	x72
Voltage	1.5V, 1.35V	1.5V, 1.35V	1.5V, 1.35V	1.5V, 1.35V	1.5V, 1.35V
PCB Height	1.18 Inches	1.18 Inches	1.18 Inches	1.18 Inches	1.18 Inches
Operating Temperature	0°C ~ 85°C	0°C ~ 85°C	0°C ~ 85°C	0°C ~ 85°C	0°C ~ 85°C

Module Type	DDR3 UDIMM WT	DDR3 SODIMM WT	DDR3 ECC UDIMM WT	DDR3 ECC SODIMM WT
Speed	1066 MT/s, 1333 MT/s, 1600 MT/s, 1866 MT/s	1066 MT/s, 1333 MT/s, 1600 MT/s, 1866 MT/s	1066 MT/s, 1333 MT/s, 1600 MT/s, 1866 MT/s	1066 MT/s, 1333 MT/s, 1600 MT/s, 1866 MT/s
Density	2GB, 4GB, 8GB	2GB, 4GB, 8GB	2GB, 4GB, 8GB	2GB, 4GB, 8GB
Function	Non-ECC Unbuffered Memory	Non-ECC Unbuffered Memory	ECC Unbuffered Memory	ECC Unbuffered Memory
Pin Number	240pin	204pin	240pin	204pin
Bus Width	x64	x64	x72	x72
Voltage	1.5V, 1.35V	1.5V, 1.35V	1.5V, 1.35V	1.5V, 1.35V
PCB Height	1.18 Inches	1.18 Inches	1.18 Inches	1.18 Inches
Operating Temperature	-40°C ~ 85°C	-40°C ~ 85°C	-40°C ~ 85°C	-40°C ~ 85°C

DDR2 DRAM Module

Module Type	DDR2 UDIMM	DDR2 SODIMM	DDR2 ECC UDIMM	DDR2 SODIMM WT
Speed	533 MT/s, 667 MT/s, 800 MT/s	533 MT/s, 667 MT/s, 800 MT/s	667 MT/s, 800 MT/s	533 MT/s, 667 MT/s, 800 MT/s
Density	1GB, 2GB, 4GB	512MB, 1GB, 2GB, 4GB	1GB, 2GB	1GB, 2GB
Function	Non-ECC Unbuffered Memory	Non-ECC Unbuffered Memory	ECC Unbuffered Memory	Non-ECC Unbuffered Memory
Pin Number	240pin	200pin	240pin	200pin
Bus Width	x64	x64	x72	x64
Voltage	1.8V	1.8V	1.8V	1.8V
PCB Height	1.18 Inches	1.18 Inches	1.18 Inches	1.18 Inches
Operating Temperature	0°C ~ 85°C	0°C ~ 85°C	0°C ~ 85°C	-40°C ~ 85°C

DDR1 DRAM Module

Module Type	DDR1 UDIMM	DDR1 SODIMM
Speed	333 MT/s, 400 MT/s	333 MT/s, 400 MT/s
Density	512MB, 1GB	256MB, 512MB, 1GB
Function	Non-ECC Unbuffered Memory	Non-ECC Unbuffered Memory
Pin Number	184pin	200pin
Bus Width	x64	x64
Voltage	2.6V	2.6V
PCB Height	1.16 inches	1.25 Inches
Operating Temperature	0°C ~ 70°C	0°C ~ 70°C

SDRAM DRAM Module

Module Type	SDRAM SODIMM
Speed	100 MT/s, 133 MT/s
Density	128MB, 256MB, 512MB
Function	Non-ECC Unbuffered Memory
Pin Number	144pin
Bus Width	x64
Voltage	3.3V
PCB Height	1.25 Inches
Operating Temperature	0°C ~ 70°C

FLASH STORAGE

PCIe – M.2

Model name	M.2 (P30) 4TE2	M.2 (P30) 4TE3	M.2 (P30) 4IE3	M.2 (P42) 3TE4		M.2 (P42) 3TE8
Connector	M Key	M Key	M Key	M Key	B+M Key	M Key
Interface	PCIe Gen 4 x4	PCIe Gen 4 x4	PCIe Gen 4 x4	PCIe Gen 3 ×4	PCIe Gen 3 ×2	PCIe Gen 3 x4
Flash Type	3D TLC	3D TLC	iSLC (3D TLC)	3D TLC		3D TLC
Capacity	128GB ~ 1TB	128GB ~ 1TB	40GB ~ 160GB	128GB ~ 1TB		128GB ~ 1TB
Max. Channel	2	2	2	4		4
Sequential R/W (MB/sec, max.)	1700/1500	1800/1450	1800/1450	2600/1800	1750/1500	3350/2600
Max. Power consumption	3.1W	3.1W	3.3W	4.0W	3.3W	4.2W
External DRAM Buffer	N	N	N	N		N
iData Guard	Y	Y	Y	N		Y
iPower Guard	Y	N	N	Y		Y
PLP (iCell)	N	N	N	N		N
AES	Y	Y	Y	Y		Y
TCG Opal	Y	Y	Y	Y		Y
S.M.A.R.T	Y	Y	Y	Y		Y
Dimension (WxLxH/mm)	ST: 22.0 x 30.0 x 3.5 WT: 25.0 x 30.0 x 15	ST: 22.0 x 30.0 x 3.5 WT: 25.0 x 30.0 x 15	ST: 22.0 x 30.0 x 3.5 WT: 25.0 x 30.0 x 15	ST: 22.0 x 42.0 x 3.0 WT: 22.0 x 42.0 x 3.6		ST: 22.0 x 42.0 x 2.8 WT: 25.0 x 42.0 x 14.5

Model name	M.2 (P42) 3IE8	M.2 (P42) 4TE2	M.2 (P42) 4IE2	M.2 (P42) 4TE3	M.2 (P42) 4IE3
Connector	M Key	M Key	M Key	M Key	M Key
Interface	PCIe Gen 3 x4	PCIe Gen 4 x4	PCIe Gen 4 x4	PCIe Gen 4 x4	PCIe Gen 4 x4
Flash Type	iSLC (3D TLC)	3D TLC	iSLC (3D TLC)	3D TLC	iSLC (3D TLC)
Capacity	40GB ~ 320GB	128GB ~ 2TB	40GB ~ 640GB	128GB ~ 2TB	40GB ~ 640GB
Max. Channel	4	4	4	4	4
Sequential R/W (MB/sec, max.)	3350/2600	3550/2950	3550/2950	3600/3150	3500/3000
Max. Power consumption	4.2W	5.0W	4.8W	4.8W	4.8W
External DRAM Buffer	N	N	N	N	N
iData Guard	Y	Y	Y	Y	Y
iPower Guard	Y	Y	Y	Y	Y
PLP (iCell)	N	N	N	N	N
AES	Y	Y	Y	Y	Y
TCG Opal	Y	Y	Y	Y	Y
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	ST: 22.0 x 42.0 x 2.8 WT: 25.0 x 42.0 x 14.5	ST: 22.0 x 42.0 x 3.5 WT: 25.0 x 42.0 x 14.5	ST: 22.0 x 42.0 x 3.5 WT: 25.0 x 42.0 x 14.5	ST: 22.0 x 42.0 x 3.5 WT: 25.0 x 42.0 x 14.5	ST: 22.0 x 42.0 x 3.5 WT: 25.0 x 42.0 x 14.5

Model name	M.2 (P80) 3TE4		M.2 (P80) 3TE8	M.2 (P80) 3IE8	InnoOSR M.2 (P80) 3TO8	M.2 (P80) 3TG3-P
Connector	M Key	B+M Key	M Key	M Key	M Key	M Key
Interface	PCIe Gen 3 ×4	PCIe Gen 3 ×2	PCIe Gen 3 x4	PCIe Gen 3 x4	PCIe Gen 3 x4	PCIe Gen 3 ×4
Flash Type	3D TLC		3D TLC	3D TLC	3D TLC	3D TLC
Capacity	128GB ~ 2TB		128GB ~ 2TB	40GB ~ 640GB	128GB ~ 2TB	128GB ~ 2TB
Max. Channel	4		4	4	4	8
Sequential R/W (MB/sec, max.)	2600/1800	1750/1500	3400/2750	3400/2750	3400/2750	3400/2800
Max. Power consumption	4.0W	3.4W	4.3W	4.3W	5.8W	6.3W
External DRAM Buffer	N		N	N	N	Y
iData Guard	N		Y	Y	Y	Y
iPower Guard	Y		Y	Y	Y	Y
PLP (iCell)	N		N	N	N	N
AES	Y		Y	Y	Y	Y
TCG Opal	Y		Y	Y	N	Y
S.M.A.R.T	Y		Y	Y	Y	Y
Dimension (WxLxH/mm)	ST: 22.0 x 80.0 x 3.0 WT: 22.0 x 80.0 x 3.6		ST: 22.0 x 80.0 x 2.15 WT: 25.0 x 80.0 x 14.5	ST: 22.0 x 80.0 x 2.15 WT: 25.0 x 80.0 x 14.5	22.0 x 80.0 x 3.5	ST: 22.0 x 80.0 x 3.95 WT: 23.6 x 80.0 x 14.65

Model name	M.2 (P80) 4TE2	M.2 (P80) 4IE2	M.2 (P80) 4TE3	M.2 (P80) 4IE3	M.2 (P80) 4TG2-P
Connector	M Key	M Key	M Key	M Key	M Key
Interface	PCIe Gen 4 x4	PCIe Gen 4 x4	PCIe Gen 4 x4	PCIe Gen 4 x4	PCIe Gen 4 x4
Flash Type	3D TLC	iSLC (3D TLC)	3D TLC	iSLC (3D TLC)	3D TLC
Capacity	128GB ~ 2TB	40GB ~ 640GB	128GB ~ 2TB	40GB ~ 640GB	256GB ~ 4TB
Max. Channel	4	4	4	4	8
Sequential R/W (MB/sec, max.)	3550/3300	3550/3300	3650/3300	3550/3200	7150/5800
Max. Power consumption	5.4W	5.1W	4.8W	4.8W	7.9W
External DRAM Buffer	N	N	N	N	Y
iData Guard	Y	Y	Y	Y	Y
iPower Guard	Y	Y	Y	Y	Y
PLP (iCell)	Y	Y	Y	Y	Y
AES	Y	Y	Y	Y	Y
TCG Opal	Y	Y	Y	Y	Y
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	ST: 22.0 x 80.0 x 3.8 WT: 25.0 x 80.0 x 14.45	ST: 22.0 x 80.0 x 3.8 WT: 25.0 x 80.0 x 14.45	ST: 22.0 x 80.0 x 3.5 WT: 25 x 80.0 x 14.45	ST: 22.0 x 80.0 x 3.5 WT: 25 x 80.0 x 14.45	ST: 22.0 x 80.0 x 4.0 WT: 25 x 80.0 x 14.45

Model name	M.2 (P80) 4TS2-P	M.2 (P80) 4IG2-P	M.2 (P110) 4TG2-P	M.2 (P110) 4TS2-P	M.2 (P110) 4IG2-P
Connector	M Key	M Key	M Key	M Key	M Key
Interface	PCIe Gen 4 x4	PCIe Gen 4 x4	PCIe Gen 4 x4	PCIe Gen 4 x4	PCIe Gen 4 x4
Flash Type	3D TLC	iSLC (3D TLC)	3D TLC	3D TLC	iSLC (3D TLC)
Capacity	200GB ~ 3.2TB	160GB ~ 1.28TB	512GB ~ 8TB	400GB ~ 6.4TB	160GB ~ 2.56TB
Max. Channel	8	8	8	8	8
Sequential R/W (MB/sec, max.)	7150/5250	7100/5250	7100 /5300	7000/5450	7000/5450
Max. Power consumption	6.2W	10.2W	10.6W	10.5W	10.5W
External DRAM Buffer	Y	Y	Y	Y	Y
iData Guard	Y	Y	Y	Y	Y
iPower Guard	Y	Y	Y	Y	Y
PLP (iCell)	Y	N	Y	Y	Y
AES	Y	Y	Y	Y	Y
TCG Opal	Y	Y	Y	Y	Y
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	ST: 22.0 x 80.0 x 4.0 WT: 25 x 80.0 x 14.45	ST: 22.0 x 80.0 x 4.0 WT: 25 x 80.0 x 14.45	ST: 22.0 x 110.0 x 4.0 WT: 25 x 110.0 x 14.45	ST: 22.0 x 110.0 x 4.0 WT: 25 x 110.0 x 14.45	ST: 22.0 x 110.0 x 4.0 WT: 25 x 110.0 x 14.45

PCIe - U.2

Model name	U.2 SSD 4TG2-P	U.2 SSD 4TS2-P	U.2 SSD 4IG2-P	U.2 SSD 5TS-P
Interface	PCIe Gen 4 ×4	PCIe Gen 4 ×4	PCIe Gen 4 ×4	PCIe Gen 5 ×4
Flash Type	3D TLC	3D TLC	iSLC (3D TLC)	3D TLC
Capacity	512GB ~ 16TB	400GB ~ 12.8TB	160GB ~ 1.28TB	1.92TB ~ 7.68TB
Max. Channel	8	8	8	16
Sequential R/W (MB/sec, max.)	7150/6150	7150/6100	7050/5200	14000/10000
Max. Power consumption	13.5W	12.6W	12.1W	22W
External DRAM Buffer	Y	Y	Y	Y
iData Guard	Y	Y	Y	Y
iPower Guard	Y	Y	Y	Y
PLP (iCell)	Y	Y	Y	Y
AES	Y	Y	Y	N
TCG Opal	Y	Y	Y	N
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	100.0 x 69.85 x 6.9	100.0 x 69.85 x 6.9	100.0 x 69.85 x 6.9	100 x 69.85 x 14.8

PCIe - CFexpress

Model name	CFexpress 4TE2	CFexpress 4TE3	CFexpress 4IE3
Interface	PCIe Gen 3 ×2	PCIe Gen 3 ×2	PCIe Gen 3 ×2
Connector	21pin	21pin	21pin
Flash Type	3D TLC	3D TLC	iSLC (3D TLC)
Capacity	128GB ~ 1TB	128GB ~ 2TB	40GB ~ 640GB
Max. Channel	4	4	4
Sequential R/W (MB/sec, max.)	1750/1650	1750/1500	1750/1650
Max. Power consumption	3.4W	3W	2.9W
iData Guard	Y	Y	Y
iPower Guard	Y	Y	Y
AES	Y	Y	Y
TCG Opal	Y	Y	Y
S.M.A.R.T	Y	Y	Y
H/W Write Protect	Y	Y	Y
Dimension (WxLxH/mm)	29.6 x 38.5 x 3.8	29.6 x 38.5 x 3.8	29.6 x 38.5 x 3.8

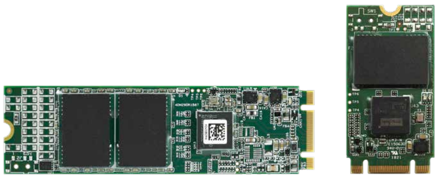
Model name	CFexpress 3TE8	CFexpress 3IE8
Interface	PCIe Gen 3 ×2	PCIe Gen 3 ×2
Connector	21pin	21pin
Flash Type	3D TLC	iSLC (3D TLC)
Capacity	128GB ~ 2TB	40GB ~ 640GB
Max. Channel	4	4
Sequential R/W (MB/sec, max.)	3400/2750	3400/2750
Max. Power consumption	5.9W	5.9W
iData Guard	Y	Y
iPower Guard	Y	Y
AES	Y	Y
TCG Opal	Y	Y
S.M.A.R.T	Y	Y
H/W Write Protect	Y	Y
Dimension (WxLxH/mm)	29.6 x 38.5 x 3.8	29.6 x 38.5 x 3.8

PCIe – EDSFF

Model name	E1.S 4TG2-P	E1.S 4TS2-P	E3.S 4TS2-P	E1.S 5TS-P	E3.S 5TS-P
Interface	PCIe Gen 4 ×4	PCIe Gen 4 ×4	PCIe Gen 4 ×4	PCIe Gen 5	PCIe Gen 5
Flash Type	3D TLC	3D TLC	3D TLC	3D TLC	3D TLC
Capacity	512GB ~ 8TB	400GB ~ 6.4TB	400GB ~ 12.8TB	1.92TB ~ 7.68TB	1.92TB ~ 7.68TB
Max. Channel	8	8	8	16	16
Sequential R/W (MB/sec, max.)	6900/4700	6900/4700	5050/4750	14000/10000	14000/10000
Max. Power consumption	12W	12W	12W	<25W	<25W
iData Guard	Y	Y	Y	Y	Y
iPower Guard	Y	Y	Y	Y	Y
AES	Y	Y	Y	N	N
TCG Opal	Y	Y	Y	N	N
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	5.9mm: 31.5 x 111.5 x 5.9 9.5mm: 33.75 x 118.75 x 9.5 15mm: 33.75 x 118.75 x 15	5.9mm: 31.5 x 111.5 x 5.9 9.5mm: 33.75 x 118.75 x 9.5 15mm: 33.75 x 118.75 x 15	76 x 112.75 x 7.5	5.9mm: 31.5 x 111.5 x 5.9 9.5mm: 33.75 x 118.75 x 9.5 15mm: 33.75 x 118.75 x 15	76 x 112.75 x 7.5

PCIe – nanoSSD

Model name	nanoSSD PCIe 4TE3
Interface	ST: PCIe Gen 4 x2 WT: PCIe Gen 3 x1
Flash Type	3D TLC
Capacity	128GB ~ 1TB
Max. Channel	4
Sequential R/W (MB/sec, max.)	3500/3300
Max. Power consumption	4.5W
External DRAM Buffer	N
iData Guard	Y
iPower Guard	Y
PLP (iCell)	N
S.M.A.R.T	Y
Dimension (WxLxH/mm)	16.0 x 20.0 x 2.0



SATA PATA – M.2

Model name	InnoOSR M.2 (S42) 3TO7	M.2 (S42) 3TE7	M.2 (S42) 3IE7	M.2 (S42) 3TEB	M.2 (S42) 3TG6-P
Connector	B+M Key	B+M Key	B+M Key	B+M Key	B+M Key
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	3D TLC	3D TLC	iSLC (3D TLC)	3D TLC	3D TLC
Capacity	32GB ~ 512GB	32GB ~ 512GB	20GB ~ 320GB	64GB ~ 2TB	128GB ~ 512GB
Max. Channel	4	4	4	2	4
Sequential R/W (MB/sec, max.)	560/330	560/330	560/530	550/510	560/510
Max. Power consumption	1.6W	1.6W	2.8W	1.2W	2.4W
External DRAM Buffer	N	N	N	N	Y
iData Guard	Y	Y	Y	Y	Y
iPower Guard	Y	Y	Y	Y	Y
PLP (iCell)	N	N	N	N	N
AES	N	N	N	N	N
TCG Opal	N	N	N	N	N
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	22.0 x 42.0 x 3.5	22.0 x 42.0 x 3.5	22.0 x 42.0 x 3.5	22.0 x 42.0 x 3.5	22.0 x 42.0 x 3.5

Model name	M.2 (S42) 3SE4	M.2 (S42) 3ME4	M.2 (S42) 3IE4	M.2 (S42) 3SE3	M.2 (S42) 3ME3
Connector	B+M Key	B+M Key	B+M Key	B+M Key	B+M Key
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	SLC	MLC	iSLC (MLC)	SLC	MLC
Capacity	8GB ~ 64GB	8GB ~ 256GB	8GB ~ 128GB	4GB ~ 32GB	8GB ~ 128GB
Max. Channel	2	2	2	4	2
Sequential R/W (MB/sec, max.)	520/360	530/210	530/380	210/110	220/80
Max. Power consumption	0.6W	1.4W	1.5W	1.2W	1.3W
External DRAM Buffer	N	N	N	N	N
iData Guard	N	N	N	Y	Y
iPower Guard	Y	Y	Y	N	N
PLP (iCell)	N	N	N	N	N
AES	N	N	N	N	N
TCG Opal	N	N	N	N	N
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	22.0 x 42.0 x 3.5	22.0 x 42.0 x 3.2	22.0 x 42.0 x 3.2	22.0 x 42.0 x 3.5	22.0 x 42.0 x 3.5

Model name	M.2 (S42) 3IE3	M.2 (S42) 3SE2-P	M.2 (S42) 3MG2-P	M.2 (S42) 3IE2-P	InnoOSR M.2 (S80) 3TO7
Connector	B+M Key	B+M Key	B+M Key	B+M Key	B+M Key
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	iSLC (MLC)	SLC	MLC	iSLC (MLC)	3D TLC
Capacity	8GB ~ 64GB	8GB ~ 64GB	32GB ~ 256GB	16GB ~ 128GB	64GB ~ 2TB
Max. Channel	2	4	4	4	4
Sequential R/W (MB/sec, max.)	240/160	520/330	560/360	560/450	560/470
Max. Power consumption	1.3W	1.6W	1.1W	1.1W	2.6W
External DRAM Buffer	N	Y	Y	Y	N
iData Guard	Y	Y	Y	Y	Y
iPower Guard	N	Y	Y	Y	Y
PLP (iCell)	N	N	N	N	N
AES	N	Y	Y	Y	N
TCG Opal	N	Y	Y	Y	N
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	22.0 x 42.0 x 3.5	22.0 x 42.0 x 3.5	22.0 x 42.0 x 3.5	22.0 x 42.0 x 3.5	22.0 x 80.0 x 3.5

Model name	M.2 (S80) 3TE7	M.2 (S80) 3IE7	M.2 (S80) 3TEB	M.2 (S80) 3TG9-P	M.2 (S80) 3TG6-P
Connector	B+M Key	B+M Key	B+M Key	B+M Key	B+M Key
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	3D TLC	iSLC (3D TLC)	3D TLC	3D TLC	3D TLC
Capacity	32GB ~ 1TB	20GB ~ 640GB	64GB ~ 1TB	512GB ~ 4TB	128GB ~ 2TB
Max. Channel	4	4	2	4	4
Sequential R/W (MB/sec, max.)	550/370	550/490	550/500	540/520	560/510
Max. Power consumption	2.0W	2.0W	1.2W	2.6W	2.6W
External DRAM Buffer	N	N	N	Y	Y
iData Guard	Y	Y	Y	Y	Y
iPower Guard	Y	Y	Y	Y	Y
PLP (iCell)	N	N	N	Y	Y
AES	Y	Y	N	Y	Y
TCG Opal	N	N	N	Y	Y
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	22.0 x 80.0 x 3.5	22.0 x 80.0 x 3.5	22.0 x 80.0 x 3.5	22.0 x 80.0 x 3.5	22.0 x 80.0 x 3.5

Model name	M.2 (S80) 3SE4	M.2 (S80) 3ME4	M.2 (S80) 3IE4	M.2 (S80) 3SE3	M.2 (S80) 3SE2-P
Connector	B+M Key	B+M Key	B+M Key	B+M Key	B+M Key
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	SLC	MLC	iSLC (MLC)	SLC	SLC
Capacity	8GB ~ 64GB	8GB ~ 256GB	8GB ~ 128GB	8GB ~ 128GB	8GB ~ 256GB
Max. Channel	2	2	2	4	4
Sequential R/W (MB/sec, max.)	520/360	530/210	530/360	380/220	520/340
Max. Power consumption	1.6W	0.9W	0.9W	2.0W	2.2W
External DRAM Buffer	N	N	N	N	Y
iData Guard	N	N	N	Y	Y
iPower Guard	Y	Y	Y	N	Y
PLP (iCell)	N	N	N	N	Y
AES	N	N	N	N	Y
TCG Opal	N	N	N	N	Y
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	22.0 x 80.0 x 2.15	22.0 x 80.0 x 3.2	22.0 x 80.0 x 3.2	22.0 x 80.0 x 3.5	22.0 x 80.0 x 3.5

Model name	M.2 (S80) 3MG2-P	M.2 (S80) 3IE2-P	M.2 (S30) 3ME4	M.2 (S60) 3ME3
Connector	B+M Key	B+M Key	B+M Key	B+M Key
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	MLC	iSLC (MLC)	MLC	MLC
Capacity	16GB ~ 1TB	32GB ~ 512GB	8GB ~ 128GB	32GB ~ 512GB
Max. Channel	4	4	2	4
Sequential R/W (MB/sec, max.)	530/450	560/450	520/120	380/200
Max. Power consumption	3.7W	3.7W	1.6W	1.3W
External DRAM Buffer	Y	Y	N	N
iData Guard	Y	Y	N	Y
iPower Guard	Y	Y	Y	N
PLP (iCell)	Y	Y	N	N
AES	Y	Y	N	N
TCG Opal	Y	Y	N	N
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	22.0 x 80.0 x 3.5	22.0 x 80.0 x 3.5	22.0 x 30.0 x 3.2	22.0 x 60.0 x 3.5

SATA PATA - 2.5"SSD

Model name	2.5" SATA SSD 3TE7	2.5" SATA SSD 3IE7	2.5" SATA SSD 3TEB	2.5" SATA SSD 3TG9-P	2.5" SATA SSD 3TS9-P
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	3D TLC	iSLC (3D TLC)	3D TLC	3D TLC	3D TLC
Capacity	32GB ~ 1TB	20GB ~ 320GB	128GB ~ 1TB	256GB ~ 8TB	256GB ~ 4TB
Max. Channel	4	4	2	4	4
Sequential R/W (MB/sec, max.)	560/525	560/525	550/500	540/520	540/520
Max. Power consumption	3.6W	3.6W	4.4W	4.0W	4.0W
External DRAM Buffer	N	N	N	Y	Y
iData Guard	Y	Y	Y	Y	Y
iPower Guard	Y	Y	Y	Y	Y
PLP (iCell)	N	N	N	Y	Y
AES	Y	Y	N	Y	Y
TCG Opal	N	N	N	Y	Y
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	69.8 x 100.10 x 6.9	69.8 x 100.10 x 6.9	69.8 x 100.1 x 6.9	69.8 x 100.10 x 6.9	69.8 x 100.10x 6.9

Model name	2.5" SATA SSD 3TG6-P	2.5" SATA SSD 3TS6-P	2.5" SATA SSD 3IE6-P	2.5" SATA SSD 3TV6-P
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	3D TLC	3D TLC	iSLC (3D TLC)	3D TLC
Capacity	128GB ~ 4TB	200GB ~ 3.2TB	80GB ~ 640GB	128GB ~ 4TB
Max. Channel	4	4	4	4
Sequential R/W (MB/sec, max.)	540 /470	540 /470	540 /470	500/460
Max. Power consumption	6.0W	4.1W	6.0W	3.5W
External DRAM Buffer	Y	Y	Y	Y
iData Guard	Y	Y	Y	Y
iPower Guard	Y	Y	Y	Y
PLP (iCell)	Y	Y	Y	Y
AES	Y	Y	Y	Y
TCG Opal	Y	Y	Y	Y
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	69.8 x 100.10 x 6.9	69.8 x 100.10 x 6.9	69.8 x 100.10 x 6.9	69.8 x 100.10 x 6.9

Model name	2.5" SATA SSD 3TR6-P	2.5" SATA SSD 3SE4	2.5" SATA SSD 3ME4	2.5" SATA SSD 3IE4
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	3D TLC	SLC	MLC	iSLC (MLC)
Capacity	128GB ~ 2TB	8GB ~ 64GB	8GB ~ 256GB	8GB ~ 128GB
Max. Channel	4	2	2	2
Sequential R/W (MB/sec, max.)	560/510	520/360	530/210	530/380
Max. Power consumption	4.2W	1.1W	0.8W	0.8W
External DRAM Buffer	Y	N	N	N
iData Guard	Y	Y	Y	Y
iPower Guard	Y	Y	Y	Y
PLP (iCell)	Y	N	N	N
AES	Y	N	N	N
TCG Opal	Y	N	N	N
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	69.8 x 100.10 x 9.5	69.85 x 100.10 x 6.9	69.8 x 100.10 x 6.9	69.8 x 100.10 x 6.9

Model name	2.5" SATA SSD 3SE2-P	2.5" SATA SSD 3MG2-P	2.5" SATA SSD 3MR2-P	InnoOSR 2.5" SATA SSD 3TO7
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	SLC	MLC	MLC	3D TLC
Capacity	8GB ~ 512GB	8GB ~ 2TB	8GB ~ 1TB	32GB ~ 2TB
Max. Channel	4	4	4	4
Sequential R/W (MB/sec, max.)	520/420	520/480	520/450	560/525
Max. Power consumption	2.2W	6.0W	6.0W	3.6 W
External DRAM Buffer	Y	Y	Y	N
iData Guard	Y	Y	Y	Y
iPower Guard	Y	Y	Y	Y
PLP (iCell)	Y	Y	Y	N
AES	Y	Y	Y	N
TCG Opal	Y	Y	Y	N
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	8GB ~ 256GB: 69.8 x 99.8 x 9.2 512GB: 69.8 x 99.8 x 9.5	8GB ~ 1TB: 69.8 x 100.1 x 6.9 2TB: 69.8 x 100.0 x 9.5	69.8 x 99.8 x 9.5	69.8 x 100.1 x 6.9

SATA PATA – SATA Slim

Model name	SATA Slim 3TE7	SATA Slim 3IE7	SATA Slim 3TG6-P	SATA Slim 3SE4	SATA Slim 3ME4	SATA Slim 3IE4	SATA Slim 3MG2-P
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	3D TLC	iSLC (3D TLC)	3D TLC	SLC	MLC	iSLC (MLC)	MLC
Capacity	32GB ~ 1TB	40GB ~ 640GB	128GB ~ 1TB	8GB ~ 64GB	8GB ~ 256GB	8GB ~ 128GB	8GB ~ 256GB
Max. Channel	4	4	4	2	2	2	4
Sequential R/W (MB/sec, max.)	550/490	550/490	560/520	520/360	530/210	530/360	520/290
Max. Power consumption	0.8W	0.8W	3.1W	1.1 W	0.8W	0.8W	2.6W
External DRAM Buffer	N	N	Y	N	N	N	Y
iData Guard	Y	Y	Y	N	N	N	Y
iPower Guard	Y	Y	Y	Y	Y	Y	Y
PLP (iCell)	N	N	N	N	N	N	N
AES	Y	Y	Y	N	N	N	Y
TCG Opal	N	N	Y	N	N	N	Y
S.M.A.R.T	Y	Y	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	54.0 x 39.0 x 4.0	54.0 x 39.0 x 4.0	54.0 x 39.0 x 4.0	54.0 x 39.0 x 4.0	54.0 x 39.0 x 4.0	54.0 x 39.0 x 4.0	54.0 x 39.0 x 4.0

SATA PATA – SATADOM

Form Factor	SATADOM-SV/SH	SATADOM-SV/SH	SATADOM-SV/SH	SATADOM-SV/SH	SATADOM-SV/SH
Model name	SATADOM 3TE7	SATADOM 3IE7	SATADOM 3ME4	SATADOM 3IE4	SATADOM 3SE4
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6Gb/s	SATA III 6Gb/s	SATA III 6Gb/s
Flash Type	3D TLC	iSLC (3D TLC)	MLC	iSLC (MLC)	SLC
Capacity	32GB ~ 256GB	20GB ~ 80GB	8GB ~ 128GB	8GB ~ 64GB	8GB ~ 32GB
Max. Channel	2	2	2	2	2
Sequential R/W (MB/sec, max.)	510/140	550/485	530/120	530/350	520/260
Max. Power consumption	1.14W	1.3W	1.27W	0.95W	1.58W
External DRAM Buffer	N	N	N	N	N
iData Guard	Y	Y	N	N	N
iPower Guard	Y	Y	Y	Y	Y
PLP (iCell)	N	N	N	N	N
AES	Y	Y	N	N	N
TCG Opal	N	N	N	N	N
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	SV: 40.4 x 21.03 x 10.4 SH: 32.7 x 18 x 14.15	SV: 40.4 x 21.03 x 10.4 SH: 32.7 x 18 x 14.15	SV: 40.4 x 21.03 x 10.4 SH: 32.7 x 18 x 15.15	SV:40.4 x 21.03 x 10.4	SV: 40.4 x 21.03 x 10.4 SH: 32.7 x 18 x 14.15

Form Factor	SATADOM-SL/SH type D	SATADOM-SL/SH type D	SATADOM-SL/SH type D	SATADOM-SL/SH type D	SATADOM-SL/SH type D
Model name	**SATADOM 3TE7**	**SATADOM 3IE7**	**SATADOM 3ME4**	**SATADOM 3IE4**	**SATADOM 3SE4**
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6Gb/s	SATA III 6Gb/s	SATA III 6Gb/s
Flash Type	3D TLC	iSLC (3D TLC)	MLC	iSLC (MLC)	SLC
Capacity	32GB ~ 256GB	20GB ~ 80GB	8GB ~ 128GB	8GB ~ 64GB	8GB ~ 32GB
Max. Channel	2	2	2	2	2
Sequential R/W (MB/sec, max.)	510/140	550/485	530/120	530/350	520/260
Max. Power consumption	1.5W	1.85W	1.02W	1.02W	0.95W
External DRAM Buffer	N	N	N	N	N
iData Guard	Y	Y	N	N	N
iPower Guard	Y	Y	Y	Y	Y
PLP (iCell)	N	N	N	N	N
AES	Y	Y	N	N	N
TCG Opal	N	N	N	N	N
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	SL: 29.6 x 33.06 x 10.5 SH(D):30 x 20.79 x 15.20	SL: 29.6 x 33.06 x 10.5 SH(D):30 x 20.79 x 15.20	SL: 29.6 x 33.06 x 10.5 SH(D): 30 x 20.79 x 15.15	SL: 29.6 x 33.06 x 10.5	SL: 29.6 x 33.06 x 10.5 SH(D):30 x 20.79 x 15.20

Form Factor	SATADOM-SH type C	SATADOM-SH type C	SATADOM-MV	SATADOM-MV	SATADOM-ML/MH
Model name	**SATADOM 3ME4**	**SATADOM 3SE4**	**SATADOM 3IE4**	**SATADOM 3ME4**	**SATADOM 3TG6-P**
Interface	SATA III 6Gb/s	SATA III 6.0Gb/s	SATA III 6Gb/s	SATA III 6Gb/s	SATA III 6.0Gb/s
Flash Type	MLC	SLC	iSLC (MLC)	MLC	3D TLC
Capacity	8GB ~ 128GB	8GB ~ 32GB	8GB ~ 64GB	8GB ~ 128GB	128GB ~ 256GB
Max. Channel	2	2	2	2	4
Sequential R/W (MB/sec, max.)	530/120	520/260	530/340	530/120	560/290
Max. Power consumption	1.02W	1.49W	1.72W	1.08W	2.14W
External DRAM Buffer	N	N	N	N	Y
iData Guard	N	N	N	N	Y
iPower Guard	Y	Y	Y	Y	Y
PLP (iCell)	N	N	N	N	N
AES	N	N	N	N	N
TCG Opal	N	N	N	N	N
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	32.7 x 18 x 14.5	32.7 x 18 x 14.5	41.55 x 25.26 x 10.4	41.55 x 25.26 x 10.4	ML: 37.17 x 31.5 x 12.6

Form Factor	SATADOM-ML/MH	SATADOM-ML/MH	SATADOM-ML/MH	SATADOM-ML/MH
Model name	**SATADOM 3MG2-P**	**SATADOM 3IE4**	**SATADOM 3ME4**	**SATADOM 3SE4**
Interface	SATA III 6.0Gb/s	SATA III 6Gb/s	SATA III 6Gb/s	SATA III 6.0Gb/s
Flash Type	MLC	iSLC (MLC)	MLC	SLC
Capacity	32GB-256GB	16GB ~ 128GB	32GB ~ 256GB	8GB ~ 64GB
Max. Channel	4	2	2	2
Sequential R/W (MB/sec, max.)	560/180	530/360	530/210	520/360
Max. Power consumption	2.68W	0.815W	0.815W	1.58W
External DRAM Buffer	Y	N	N	N
iData Guard	Y	Y	N	N
iPower Guard	Y	Y	Y	Y
PLP (iCell)	N	N	N	N
AES	N	N	N	N
TCG Opal	N	N	N	N
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	ML: 37.17 x 31.5 x 12.6	ML: 31.2 x 36.7 x 10.7 MH: 23.5 x 33.6 x 14.8	ML: 31.2 x 36.7 x 10.7 MH: 23.5 x 33.6 x 14.8	ML: 36.7 x 31.2 x 10.7

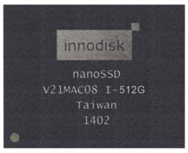
SATA PATA – mSATA

Model name	mSATA 3TE7	mSATA 3IE7	mSATA 3TG6-P	mSATA 3SE4	mSATA 3ME4	mSATA 3IE4
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	3D TLC	iSLC (3D TLC)	3D TLC	SLC	MLC	iSLC (MLC)
Capacity	32GB ~ 1TB	20GB ~ 640GB	128GB ~ 1TB	8GB ~ 64GB	8GB ~ 256GB	8GB ~ 128GB
Max. Channel	4	4	4	2	2	2
Sequential R/W (MB/sec, max.)	560/525	550 / 490	560/510	525/350	535/210	530/365
Max. Power consumption	2.2W	2.7W	2.8W	1.4W	0.6W	0.6W
External DRAM Buffer	N	N	Y	N	N	N
iData Guard	Y	Y	Y	N	N	N
iPower Guard	Y	Y	Y	Y	Y	Y
PLP (iCell)	Y	N	N	N	N	N
AES	Y	Y	Y	N	N	N
TCG Opal	N	N	Y	N	N	N
S.M.A.R.T	Y	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	29.8 x 50.8 x 3.7	29.8 x 50.8 x 3.7	29.8 x 50.8 x 3.7	29.8 x 50.8 x 3.7	29.8 x 50.8 x 3.7	29.8 x 50.8 x 3.7

Model name	mSATA 3MG2-P	mSATA mini 3TE7	mSATA mini 3IE7	mSATA mini 3SE4	mSATA mini 3ME4	mSATA mini 3IE4
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	MLC	3D TLC	iSLC (3D TLC)	SLC	MLC	iSLC (MLC)
Capacity	8GB ~ 512GB	32GB ~ 256GB	20GB ~ 320GB	8GB ~ 64GB	8GB ~ 128GB	8GB ~ 64GB
Max. Channel	4	4	4	2	2	2
Sequential R/W (MB/sec, max.)	520/450	560/520	560/520	525/360	430/125	530/340
Max. Power consumption	2.2W	0.6W	2.8W	1.3W	0.6W	0.6W
External DRAM Buffer	Y	N	N	N	N	N
iData Guard	Y	Y	Y	N	N	N
iPower Guard	Y	Y	Y	Y	Y	Y
PLP (iCell)	N	N	N	N	N	N
AES	Y	Y	Y	N	N	N
TCG Opal	Y	N	N	N	N	N
S.M.A.R.T	Y	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	29.85 x 50.8 x3.6	30 x 26.8 x 3.6	30 x 26.8 x 3.6	30 x 26.8 x 3.6	30 x 26.8 x 3.4	30 x 26.8 x 3.4

SATA PATA – CFast

Model name	CFast 3TE7	CFast 3IE7	CFast 3SE4	CFast 3ME4	CFast 3IE4	CFast 3MG2-P
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	3D TLC	iSLC (3D TLC)	SLC	MLC	iSLC	MLC
Capacity	32GB ~ 512GB	20GB ~ 320GB	8GB ~ 64GB	8GB ~ 256GB	8GB ~ 128GB	32GB ~ 256GB
Max. Channel	4	4	2	2	2	4
Sequential R/W (MB/sec, max.)	560/520	550/490	520/360	530/210	530/360	560/350
Max. Power consumption	1.8W	1.8W	1.6W	0.9W	0.8W	2.5W
External DRAM Buffer	N	N	N	N	N	Y
iData Guard	Y	Y	N	N	N	Y
iPower Guard	Y	Y	Y	Y	Y	Y
PLP (iCell)	N	N	N	N	N	N
AES	Y	Y	N	N	N	N
TCG Opal	N	N	N	N	N	N
S.M.A.R.T	Y	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	42.8 x 36.4 x 3.6	42.8 x 36.4 x 3.6	42.8 x 36.4 x 3.6	42.8 x 36.4 x 3.6	42.8 x 36.4 x 3.6	42.8 x 36.4 x 3.6

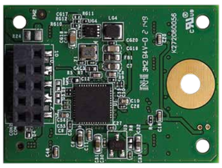


SATA PATA – nanoSSD

Model name	nanoSSD 3ME3	nanoSSD 3IE3	nanoSSD 3TE7
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	MLC	iSLC (MLC)	3D TLC
Capacity	16GB	16GB	32GB ~ 256GB
Max . Channel	4	4	4
Sequential R/W (MB/sec, max .)	410/140	440/260	540/260
Max . Power consumption	2.3W	2.3W	1.9W
External DRAM Buffer	N	N	N
iData Guard	Y	Y	N
iPower Guard	Y	Y	N
PLP (iCell)	N	N	N
S.M.A.R.T	Y	Y	Y
Dimension (WxLxH/mm)	16.0 x 20.0 x 1.7	16.0 x 20.0 x 1.7	16.0 x 20.0 x 1.7

SATA PATA – CF

Model name	iCF 9000	iCF 1SE	iCF 1ME	iCF 1ME2	iCF 1SE2	iCF 1SE3
Interface	PATA	PATA	PATA	PATA	PATA	PATA
Connector	50pin CF connector	50pin CF connector	50pin CF connector	50pin CF connector	50pin CF connector	50pin CF connector
Flash Type	SLC	SLC	MLC	MLC	SLC	SLC
Capacity	1GB ~ 64GB	512MB ~ 8GB	8GB ~ 256GB	8GB ~ 256GB	1GB ~ 64GB	128MB ~ 64GB
Max. Channel	4	2	2	2	2	2
Sequential R/W (MB/sec, max.)	110/100	40/30	110/110	85/55	75/65	63/55
Max. Power consumption	0.95W(5V x 190mA) 0.63W(3.3V x 190mA)	0.75W(5V x 150mA) 0.5W(3.3V x 150mA)	0.76w(5V x 155mA) 0.52W(3.3V x 155 mA)	0.85W(5Vx170mA)	1.4W(5V x 280mA)	0.7W (5V x 140mA)
External DRAM Buffer	N	N	N	N	N	N
iData Guard	N	N	N	N	N	N
iPower Guard	N	N	N	N	N	N
PLP (iCell)	N	N	N	N	N	N
AES	N	N	N	N	N	N
TCG Opal	N	N	N	N	N	N
S.M.A.R.T	Y	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	42.8 x 36.4 x 3.3	42.8 x 36.4 x 3.3	42.8 x 36.4 x 3.3	42.8 x 36.4 x 3.3	42.8 x 36.4 x 3.3	42.8 x 36.4 x 3.3



SATA PATA – EDC

Form Factor	EDC Vertical	EDC Vertical	EDC Horizontal	EDC Horizontal
Model name	EDC 1ME Vertical Type	EDC 1SE Vertical Type	EDC 1SE Horizontal Type	EDC 1ME Horizontal Type
Interface	PATA	PATA	PATA	PATA
Connector	44 pin	40/44 pin	40/44 pin A~F type	44 pin A~F type
Flash Type	MLC	SLC	SLC	MLC
Capacity	8GB ~ 128GB	512MB ~ 4GB	512MB ~ 8GB	8GB ~ 256GB
Max. Channel	2	2	2	2
Sequential R/W (MB/sec, max.)	110/75	40/28	40/28	110/75
Max. Power consumption	1.05W(5V x 150mA) 0.69W(3.3V x 150mA)	0.75W(5V x 150mA) 0.5W(3.3V x 150mA)	0.75W(5V x 150mA) 0.5W(3.3V x 150mA)	1.05W(5V x 150mA) 0.69W(3.3V x 150mA)
External DRAM Buffer	N	N	N	N
iData Guard	N	N	N	N
iPower Guard	N	N	N	N
PLP (iCell)	N	N	N	N
AES	N	N	N	N
TCG Opal	N	N	N	N
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	50.3 x 27.3 x 7.5	40 pin: 60.2 x 27.3 x 6.4 44 pin: 50.3 x 27.3 x 5.8	40 pin: 55 x 32.4 x 18.3 44 pin: 48 x 32.6 x 12.9 (for different connectors, the dimensions may have slight differences)	48 x 32.6 x 7.3 (for different connectors, the dimensions may have slight differences)

Others – USB

Form Factor	USB Drive	USB Drive	USB Drive	USB Drive
Model name	USB Drive 2SE2	USB Drive 2ME2	USB Drive 3SE	USB Drive 3ME
Interface	USB 2.0	USB 2.0	USB 3.0	USB 3.0
Connector	Type A	Type A	Type A	Type A
Flash Type	SLC	MLC	SLC	MLC
Capacity	512MB ~ 16GB	8GB ~ 64GB	4GB ~ 32GB	8GB ~ 64GB
Max. Channel	1	1	1	1
Sequential R/W (MB/sec, max.)	30/30	40/30	100/85	100/50
Max. Power consumption	0.35 W	0.43W	0.70 W	0.70W
External DRAM Buffer	N	N	N	N
iData Guard	Y	Y	N	N
iPower Guard	Y	Y	Y	N
PLP (iCell)	N	N	N	N
AES	N	N	N	N
TCG Opal	N	N	N	N
S.M.A.R.T	N	N	Y	Y
Dimension (WxLxH/mm)	16.60 x 61.45 x 7.60	16.60 x 61.45 x 7.60	16.6 x 48.55 x 7.6	16.6 x 48.55 x 7.6

Form Factor	USB Drive	USB EDC Horizontal	USB EDC Horizontal	USB EDC Horizontal
Model name	USB Drive 3IE4	USB EDC H 2SE2	USB EDC H 2ME2	USB EDC H 2ME3
Interface	USB 3.0	USB 2.0	USB 2.0	USB 2.0
Connector	Type A	Standard, 9pin, 2.54mm Low profile, 9pin, 2.00mm	Standard, 9pin, 2.54mm Low profile, 9pin, 2.00mm	Standard, 9pin, 2.54mm Low profile, 9pin, 2.00mm
Flash Type	iSLC (3D TLC)	SLC	MLC	MLC
Capacity	16GB ~ 128GB	512MB ~ 32GB	4GB ~ 64GB	8GB ~ 32GB
Max. Channel	2	1	1	1
Sequential R/W (MB/sec, max.)	330/125	30/20	40/25	35/35
Max. Power consumption	1.3W	0.51W	0.45W	0.66W
External DRAM Buffer	N	N	N	N
iData Guard	Y	Y	Y	Y
iPower Guard	Y	Y	Y	Y
PLP (iCell)	N	N	N	N
AES	N	N	N	N
TCG Opal	N	N	N	N
S.M.A.R.T	Y	N	N	N
Dimension (WxLxH/mm)	16.6 x 48.55 x 7.6	26.6 x 36.9 x 6.75 (Pin Pitch 2.00mm) 26.6 x 36.9 x 9.85 (Pin Pitch 2.54mm)	26.6 x 36.9 x 6.75 (Pin Pitch 2.00mm) 26.6 x 36.9 x 9.85 (Pin Pitch 2.54mm)	26.6 x 36.9 x 6.36 (Pin Pitch 2.00mm) 26.6 x 36.9 x 9.85 (Pin Pitch 2.54mm)

Form Factor	USB EDC Horizontal	USB EDC Vertical	USB EDC Vertical	USB EDC Vertical
Model name	**USB EDC H 3IE4**	**USB EDC V 2SE2**	**USB EDC V 3SE**	**USB EDC V 3ME**
Interface	USB 3.0	USB 2.0	USB 3.0	USB 3.0
Connector	Standard, 9pin, 2.54mm Low profile, 9pin, 2.00mm	Standard, 9pin	Standard, 20pin, 2.00mm	Standard, 20pin, 2.00mm
Flash Type	iSLC (3D TLC)	SLC	SLC	MLC
Capacity	16GB ~ 128GB	512MB ~ 16GB	4GB ~ 32GB	8GB ~ 64GB
Max. Channel	2	1	1	1
Sequential R/W (MB/sec, max.)	330/125	30/30	110/85	100/50
Max. Power consumption	1.3W	0.54W	0.79W	0.79W
External DRAM Buffer	N	N	N	N
iData Guard	Y	Y	N	N
iPower Guard	Y	Y	N	Y
PLP (iCell)	N	N	N	N
AES	N	N	N	N
TCG Opal	N	N	N	N
S.M.A.R.T	Y	N	Y	Y
Dimension (WxLxH/mm)	26.6 x 36.9 x 6.36 (Pin Pitch 2.00mm) 26.6 x 36.9 x 9.85 (Pin Pitch 2.54mm)	14.0 x 41.5 x 6.0	24.0 x 22.0 x 5.0	24.0 x 22.0 x 5.0

Others – SD

Model name	MicroSD 3TE4	MicroSD 3IE4	MicroSD 3SE3	MicroSD 3ME3	MicroSD 3ME2
Interface	SD 3.0/6.1	SD 3.0/6.1	SD 3.0	SD 3.0	SD 3.0
Flash Type	3D TLC	iSLC (3D TLC)	SLC	MLC	MLC
Capacity	32GB ~ 512GB	8GB ~ 128GB	4GB ~ 8GB	8GB ~ 64GB	8GB ~ 64GB
Max. Channel	1	1	1	1	1
Sequential R/W (MB/sec, max.)	95/85	95/85	30/23	76/52	76/32
Max. Power consumption	0.6W	0.4W	0.2W	0.5W	0.7W
External DRAM Buffer	N	N	N	N	N
iData Guard	N	N	N	N	N
iPower Guard	N	N	N	N	N
PLP (iCell)	N	N	N	N	N
AES	N	N	N	N	N
TCG Opal	N	N	N	N	N
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	11.0 x 15.0 x 1.0	11.0 x 15.0 x 1.0	11.0 x 15.0 x 1.0	11.0 x 15.0 x 1.0	11.0 x 15.0 x 1.0

Model name	MicroSD 3IE2	Industrial MicroSD Card	SD Card 3TE4	SD Card 3IE4
Interface	SD 3.0	SD 1.0/2.0	SD 3.0/6.1	SD 3.0/6.1
Flash Type	iSLC (MLC)	SLC	3D TLC	iSLC (3D TLC)
Capacity	4GB ~ 32GB	1GB ~ 8GB	32GB ~ 256GB	8GB ~ 64GB
Max. Channel	1	1	1	1
Sequential R/W (MB/sec, max.)	79/45	20/16	95/85	95/85
Max. Power consumption	0.7W	0.2W	0.5W	0.4W
External DRAM Buffer	N	N	N	N
iData Guard	N	N	N	N
iPower Guard	N	N	N	N
PLP (iCell)	N	N	N	N
AES	N	N	N	N
TCG Opal	N	N	N	N
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	11.0 x 15.0 x 1.0	11.0 x 15.0 x 1.0	24.0 x 32.0 x 2.1	24.0 x 32.0 x 2.1

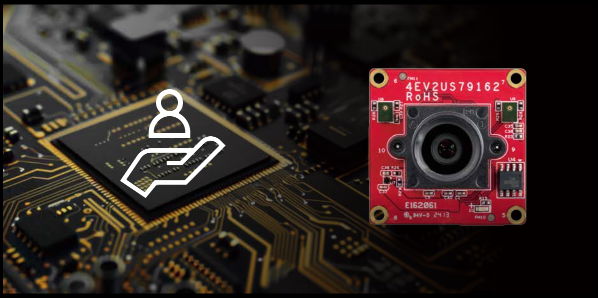
Model name	SD Card 3SE6	SD Card 3SE3	SD Card 3ME3	SD Card 3IE3
Interface	SD 2.0	SD 3.0	SD 3.0	SD 3.0
Flash Type	SLC	SLC	MLC	iSLC (MLC)
Capacity	512MB ~ 2GB	4GB ~ 32GB	8GB ~ 128GB	4GB ~ 64GB
Max. Channel	1	1	1	1
Sequential R/W (MB/sec, max.)	23/20	37/31	80/46	79/70
Max. Power consumption	0.3W	0.4W	0.5W	0.5W
External DRAM Buffer	N	N	N	N
iData Guard	N	N	N	N
iPower Guard	N	N	N	N
PLP (iCell)	N	N	N	N
AES	N	N	N	N
TCG Opal	N	N	N	N
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	24.0 x 32.0 x 2.1	24.0 x 32.0 x 2.1	24 x 32.0 x 2.1	24.0 x 32.0 x 2.1

SENSING INTELLIGENCE

SENSING INTELLIGENCE

물리적 환경에서 정확하고 신뢰할 수 있는 이미지와 데이터를 캡처합니다 . 지능형 모듈은 엣지에서 인텔리전스 애플리케이션을 시작합니다 .

CAMERA MODULE 카메라 설계 서비스

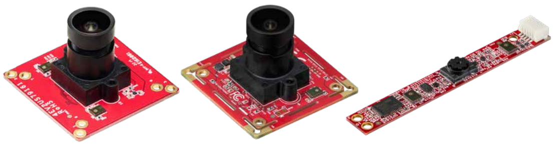


Hardware (PCBA, Size)

Versatile Lens Selection

Image Quality Tuning

Platform Integration



USB2.0

Model Name	EV2U-SGR1-MMC1	EV2U-RMR1-UMCB	EV2U-RMR2-MMC1	EV2U-SSM1-RLCF
Module Type	USB 2.0 2MP Fixed Focus Camera Module	USB 2.0 2MP Fixed Focus Camera Module	USB 2.0 2MP Fixed Focus Camera Module	USB 2.0 2MP Fixed Focus Camera Module
Resolution (Max.)	2MP	2MP	2MP	2MP
Frame Rate (Max. Resolution)	30fps	30fps	30fps	30fps
Output I/F	USB 2.0	USB 2.0	USB 2.0	USB 2.0
Sensor	GalaxyCore GC2053	OmniVision OV2740	OmniVision OV2732	Sony IMX307
Shutter	Rolling	Rolling	Rolling	Rolling
Video Format	YUV422, MJPEG	YUV422, MJPEG	YUV422, MJPEG	YUV422, MJPEG
Power Consumption	Approximate 1W (MJPEG @Max. Resolution)	Approximate 1W (MJPEG @Max. Resolution)	Approximate 1W (MJPEG @Max. Resolution)	Approximate 1W (MJPEG @Max. Resolution)
Operating Temperature	-20°C ~ 70°C	-20°C ~ 70°C	-20°C ~ 70°C	-20°C ~ 70°C
Sensor Size	1/2.9"	1/6"	1/6"	1/2.8"
Pixel Size	2.8μm	1.4μm	1.4μm	2.9μm
Chroma Type	Color	Color	Color	Color
Lens Type	Fixed Focus (M12)	Fixed Focus (M5)	Fixed Focus (M12)	Fixed Focus (M12)
Dimension (WxLxH/mm)	38 x 38 x 26.6	60 x 8 x 3.85	58 x 25 x 27	38 x 38 x 26.6 41.4 x 41.4 x TBC (Housing)
Lens FOV(D/H/V)	121° / 102° / 54°	77.3° / 69.8° / 42.7°	86° / 72° / 38°	121° / 102° / 54°
OS Support	Windows/ Linux/ Android/ macOS	Windows/ Linux/ Android/ macOS	Windows/ Linux/ Android/ macOS	Windows/ Linux/ Android/ macOS
Housing	Board Level	Board Level	Board Level	Board Level, Housing
Features	Low Light, DMIC	DMIC	DMIC	Low Light, DMIC, External Trigger
Warranty	3 Years	3 Years	3 Years	3 Years

For detailed resolution and frame rate combined application, please refer to product datasheet.

Model Name	EV2U-LOM1-RHCF	EV8U-LSM1-RLCF	EV8U-LSM1-RLCN	EV8U-LSM1-RLCA
Module Type	USB 2.0 2MP Fixed Focus Camera Module	USB 2.0 8MP Fixed Focus Camera Module	USB 2.0 8MP Fixed Focus Camera Module	USB 2.0 8MP Auto Focus Camera Module
Resolution (Max.)	2MP	8MP	8MP	8MP
Frame Rate (Max. Resolution)	30fps	30fps	30fps	30fps
Output I/F	USB 2.0	USB 2.0	USB 2.0	USB 2.0
Sensor	onsemi AR0246	Sony IMX415	Sony IMX415	Sony IMX415
Shutter	Rolling	Rolling	Rolling	Rolling
Video Format	YUV422, MJPEG	YUV422, MJPEG	YUV422, MJPEG	YUV422, MJPEG
Power Consumption	Approximate 1W (MJPEG @Max. Resolution)	Approximate 1W (MJPEG @Max. Resolution)	Approximate 1W (MJPEG @Max. Resolution)	Approximate 1W (MJPEG @Max. Resolution)
Operating Temperature	0°C ~ 70°C	0°C ~ 70°C	0°C ~ 70°C	0°C ~ 70°C
Sensor Size	1/4"	1/2.8"	1/2.8"	1/2.8"
Pixel Size	2.0µm	1.45µm	1.45µm	1.45µm
Chroma Type	Color	Color	Color	Color
Lens Type	Fixed Focus (M12)	Fixed Focus (M12)	Fixed Focus (M12)	Fixed Focus (M12)
Dimension (WxLxH/mm)	38 x 38 x TBC 41.4 x 41.4 x TBC (Housing)	38 x 38 x TBC 41.4 x 41.4 x TBC (Housing)	38 x 38 x TBC 41.4 x 41.4 x TBC (Housing)	38 x 38 x TBC 41.4 x 41.4 x TBC (Housing)
Lens FOV(D/H/V)	TBC	89° / 81° / 51°	106° / 89.5° / 48.4°	TBC
OS Support	Windows/ Linux/ Android/ macOS	Windows/ Linux/ Android/ macOS	Windows/ Linux/ Android/ macOS	Windows/ Linux/ Android/ macOS
Housing	Board Level, Housing	Board Level, Housing	Board Level, Housing	Board Level, Housing
Features	HDR, DMIC	Low Light, DMIC	Low Light, Night Vision	Low Light, DMIC
Warranty	3 Years	3 Years	3 Years	3 Years

For detailed resolution and frame rate combined application, please refer to product datasheet.

MIPI CSI-2

Model Name	EV2M-GOM1-MUCA	EV2M-ZOM1-GSCV	EV2M-OOM1-UHCA	EV2M-OOM2-RLCF	EV2M-OOM3-RHCF
Module Type	MIPI CSI-2 2MP Fixed Focus Camera Module	MIPI CSI-2 2.3MP Varifocal Focus Camera Module	MIPI CSI-2 2.3MP Fixed Focus Camera Module	MIPI CSI-2 2MP Fixed Focus Camera Module	MIPI CSI-2 2MP Fixed Focus Camera Module
Resolution (Max.)	2MP	2.3MP	2.3MP	2MP	2MP
Frame Rate (Max. Resolution)	30fps	60fps	60fps	60fps	30fps
Output I/F	MIPI CSI-2	MIPI CSI-2	MIPI CSI-2	MIPI CSI-2	MIPI CSI-2
Sensor	onsemi AR0330	onsemi AR0234	onsemi AR0234	onsemi AR0221	onsemi AR0246
Shutter	Rolling	Global	Global	Rolling	Rolling
Video Format	YUV422	YUV422	YUV422	YUV422	YUV422
Power Consumption	Approximate 1.6W (YUV422 @Max. Resolution)	Approximate 2W (YUV422 @Max. Resolution)	Approximate 1W (YUV422 @Max. Resolution)	Approximate 1W (YUV422 @Max. Resolution)	Approximate 1W (YUV422 @Max. Resolution)
Operating Temperature	-30°C ~ 70°C	-20°C ~ 65°C	-30°C ~ 70°C	-30°C ~ 70°C	-30°C ~ 70°C
Sensor Size	1/3"	1/2.6"	1/2.6"	1/1.7"	1/4"
Pixel Size	2.2µm	3.0µm	3.0µm	4.2µm	2.0µm
Chroma Type	Color	Color	Color	Color	Color
Lens Type	Fixed Focus (M12)	Varifocal	Fixed Focus (M12)	Fixed Focus (M12)	Fixed Focus (M12)
Dimension (WxLxH/mm)	38 x 38 x 45 46 x 46 x 45 (Open Front Housing)	42 x 42 x 77.7	38 x 38 x 26.75 46 x 46 x 26.75 (Open Front Housing)	30 x 30 x 48.27 39 x 39 x 48.27 (Open Front Housing)	30 x 30 x TBC 39 x 39 x TBC (Open Front Housing)
Lens FOV(D/H/V)	230°	W: 128.1 ° / 103.1 ° / 60.6° T: 39.9 ° / 33.8 ° / 21.1°	104° / 86° / 46°	122° / 113° / 75°	96° / 88° / 57°
OS Support	NVIDIA Jetson Orin, Intel	NVIDIA Jetson Orin	NVIDIA Jetson Orin, Intel	NVIDIA Jetson Orin, Intel	NVIDIA Jetson Orin, Intel
Housing	Board Level, Open Front Housing	Board Level	Board Level, Open Front Housing	Board Level, Open Front Housing	Board Level, Open Front Housing
Features	Fisheye Dewarping			Low light, External Trigger	HDR, External Trigger
Warranty	3 Years	3 Years	3 Years	3 Years	3 Years

For detailed resolution and frame rate combined application, please refer to product datasheet.
For more platform support, please contact our local sales.

Model Name	EV2M-CSM1-RHCF	EV5M-CSM1-RTCF	EV8M-CSM1-RTCF	EV8M-OOM1-RHCF	EVDM-OOM1-RHCF
Module Type	MIPI CSI-2 2MP Fixed Focus Camera Module	MIPI CSI-2 5MP Fixed Focus Camera Module	MIPI CSI-2 8MP Fixed Focus Camera Module	MIPI CSI-2 8MP Fixed Focus Camera Module	MIPI CSI-2 13MP Fixed Focus Camera Module
Resolution (Max.)	2MP	5MP	8MP	8MP	13MP
Frame Rate (Max. Resolution)	120fps	30fps	30fps	30fps	20fps
Output I/F	MIPI CSI-2	MIPI CSI-2	MIPI CSI-2	MIPI CSI-2	MIPI CSI-2
Sensor	Sony IMX290	Sony IMX335	Sony IMX415	onsemi AR0822	onsemi AR1335
Shutter	Rolling	Rolling	Rolling	Rolling	Rolling
Video Format	YUV422	YUV422	YUV422	YUV422	YUV422
Power Consumption	Approximate 1.5W (YUV422 @Max. Resolution)	Approximate 1.6W (YUV422 @Max. Resolution)	Approximate 1.9W (YUV422 @Max. Resolution)	Approximate 1W (YUV422 @Max. Resolution)	Approximate 1W (YUV422 @Max. Resolution)
Operating Temperature	-20°C ~ 65°C	-20°C ~ 65°C	-20°C ~ 65°C	-30°C ~ 70°C	-30°C ~ 70°C
Sensor Size	1/2.8"	1/2.8"	1/2.8"	1/1.8"	1/3.2"
Pixel Size	2.9μm	2.0μm	1.45μm	2.0μm	1.1μm
Chroma Type	Color	Color	Color	Color	Color
Lens Type	Fixed Focus (M12)	Fixed Focus (M12)	Fixed Focus (M12)	Fixed Focus (M12)	Fixed Focus (M12)
Dimension (WxLxH/mm)	46 x 46 x 40.6 (Open Front Housing)	46 x 46 x 40.6 (Open Front Housing)	46 x 46 x 40.6 (Open Front Housing)	30 x 30 x 41.2 39 x 39 x 41.2 (Open Front Housing)	30 x 30 x 40.5 39 x 39 x 40.5 (Open Front Housing)
Lens FOV(D/H/V)	107° / 93° / 52°	126° / 97° / 73°	148° / 125° / 67°	107° / 100° / 67°	91° / 71° / 52°
OS Support	NVIDIA Jetson Orin	NVIDIA Jetson Orin	NVIDIA Jetson Orin	NVIDIA Jetson Orin, Intel	NVIDIA Jetson Orin, Intel
Housing	Open Front Housing	Open Front Housing	Open Front Housing	Board Level, Open Front Housing	Board Level, Open Front Housing
Features	HDR, Low light	HDR, Low light	HDR, Low light	HDR, External Trigger	HDR
Warranty	3 Years	3 Years	3 Years	3 Years	3 Years

For detailed resolution and frame rate combined application, please refer to product datasheet.
For more platform support, please contact our local sales.

MIPI over Type-C

Model Name	EV2C-GOM1-RSCO	EV2C-OOM2-RLCF	EV2C-OOM3-RHCF	EV8C-OOM1-RHCF
Module Type	MIPI over Type-C 2MP Fixed Focus Camera Module	MIPI over Type-C 2MP Fixed Focus Camera Module	MIPI over Type-C 2MP Fixed Focus Camera Module	MIPI over Type-C 8MP Fixed Focus Camera Module
Resolution (Max.)	2MP	2MP	2MP	8MP
Frame Rate (Max. Resolution)	30fps	60fps	30fps	30fps
Output I/F	MIPI over Type-C	MIPI over Type-C	MIPI over Type-C	MIPI over Type-C
Sensor	onsemi AR0330	onsemi AR0221	onsemi AR0246	onsemi AR0822
Shutter	Rolling	Rolling	Rolling	Rolling
Video Format	YUV422	YUV422	YUV422	YUV422
Power Consumption	Approximate 1.6W (YUV422 @Max. Resolution)	Approximate 1W (YUV422 @Max. Resolution)	Approximate 1W (YUV422 @Max. Resolution)	Approximate 1W (YUV422 @Max. Resolution)
Operating Temperature	-30°C ~ 70°C	-30°C ~ 70°C	-30°C ~ 70°C	-30°C ~ 70°C
Sensor Size	1/3"	1/1.7"	1/4"	1/1.8"
Pixel Size	2.2μm	4.2μm	2.0μm	2.0μm
Chroma Type	Color	Color	Color	Color
Lens Type	Fixed Focus (M12)	Fixed Focus (M12)	Fixed Focus (M12)	Fixed Focus (M12)
Dimension (WxLxH/mm)	38 x 38 x TBC 41.4 x 41.4 x TBC (Housing)	30 x 30 x TBC 41.4 x 41.4 x TBC (Housing)	30 x 30 x TBC 41.4 x 41.4 x TBC (Housing)	30 x 30 x TBC 41.4 x 41.4 x TBC (Housing)
Lens FOV(D/H/V)	230°	122° / 113° / 75°	96°/88°/57°	107°/100°/67°
OS Support	NVIDIA Jetson Orin, Intel	NVIDIA Jetson Orin, Intel	NVIDIA Jetson Orin, Intel	NVIDIA Jetson Orin, Intel
Housing	Board Level, Housing	Board Level, Housing	Board Level, Housing	Board Level, Housing
Features	Fisheye Dewarping	Low Light	HDR	HDR
Warranty	3 Years	3 Years	3 Years	3 Years

For detailed resolution and frame rate combined application, please refer to product datasheet.
For more platform support, please contact our local sales.

GMSL2

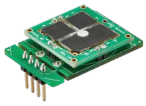
Model Name	EVDM-OOM1-RHCF
Module Type	GMSL2 13MP Fixed Focus Camera Module
Resolution (Max.)	13MP
Frame Rate (Max. Resolution)	20fps
Output I/F	FAKRA Z
Sensor	onsemi AR1335
Serializer	MAX9295A
Shutter	Rolling
Video Format	YUV422
Power Consumption	Approximate 1W (YUV422 @Max. Resolution)
Operating Temperature	-30°C ~ 70°C
Sensor Size	1/3.2"
Pixel Size	1.1µm
Chroma Type	Color
Lens Type	Fixed Focus (M12)
Dimension (WxLxH/mm)	42 x 41 x 53.3
Lens FOV (D / H / V)	91° / 71° / 52°
Platform Support	NVIDIA Jetson Orin
Housing	IP67 Housing
Features	HDR
Warranty	3 Years

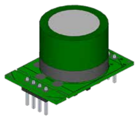
For detailed resolution and frame rate combined application, please refer to product datasheet.
For more platform support, please contact our local sales.

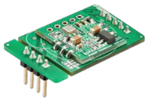
AIR SENSOR MODULE

Air Sensor

Model	IAGM2	IAGCO2	IAGM1	IAGNO2
Detection	PM2.5 , PM10	Carbon dioxide (CO2)	Formaldehyde (HCHO)	Nitrogen dioxide (NO2)
Principle	Optical scattering(Laser)	Non-dispersive infrared (NDIR)	Electrochemical	Electrochemical
Measurement range	0 ~ 1000 μ g/m3	0 ~ 5000 ppm	0.01 ~ 5 ppm	0 ~ 20 ppm
Resolution	1 μ g/m3	1 ppm	0.01 ppm	0.1 ppm
Accuracy	±10±10% of reading μ g/m3	±30±3% of reading ppm	±0.02±10% of reading ppm	±2% FS ppm
Response Time(T90) (sec)	<10 sec	<120 sec	<30 sec	<30 sec
Operation Temperature(°C)	-10 ~ 50 °C	-10 ~ 50 °C	-10 ~ 50 °C	-10 ~ 50 °C
Operation Humidity (% RH)	15 to 90 %RH	15 to 90 %RH	15 to 90 %RH	15 to 90 %RH
Expected Operating Fife(year)	3 Years	3 Years	3 Years	2 Years
Power Supply(V)	4.75 ~ 5.25 V	VDD : 4.8 ~ 5.2 V VDDIO : 3.1 ~ 3.5 V	3.1 ~ 3.5V	3.1 ~ 3.5V
Power Consumption(mW)	110 mW	150 mW	<100 mW	<100 mW
Interface	I^2C	I^2C	I^2C	I^2C
Dimension(mm)	58(L) 48(W) 15.5(H)	37(L) 21(W) 14(H)	32(L) 25(W) 10(H)	32(L) 21(W) 21(H)







Model	IAGO3	IAGSO2	IAGVOC	IAGCO
Detection	Ozone (O3)	Sulfur dioxide (SO2)	Total volatile organic compounds (TVOC)	carbon monoxide (CO)
Principle	Electrochemical	Electrochemical	MEMS	Electrochemical
Measurement range	0 ~ 5 ppm	0 ~ 20 ppm	0 ~ 60 ppm	0 ~ 1000 ppm
Resolution	0.01 ppm	0.1 ppm	0.01 ppm	0.1 ppm
Accuracy	±0.1±10% of reading ppm	±5% FS ppm	±0.1±10% of reading ppm	±5±5% of reading ppm
Response Time(T90) (sec)	<60 sec	<30 sec	<10 sec	<30 sec
Operation Temperature(°C)	-10 ~ 50 °C	-10 ~ 50 °C	-10 ~ 50 °C	-10 ~ 50 °C
Operation Humidity (% RH)	15 to 90 %RH	15 to 90 %RH	15 to 90 %RH	15 to 90 %RH
Expected Operating Fife(year)	3 Years	2 Years	1 Year	3 Years
Power Supply(V)	3.1 ~ 3.5V	3.1 ~ 3.5V	3.1 ~ 3.5V	3.1 ~ 3.5V
Power Consumption(mW)	<100 mW	<100	<100	<100
Interface	I^2C	I^2C	I^2C	I^2C
Dimension(mm)	32(L) 21(W) 8(H)	32(L) 21(W) 21(H)	32(L) 21(W) 7(H)	32(L) 21(W) 11(H)

Specification

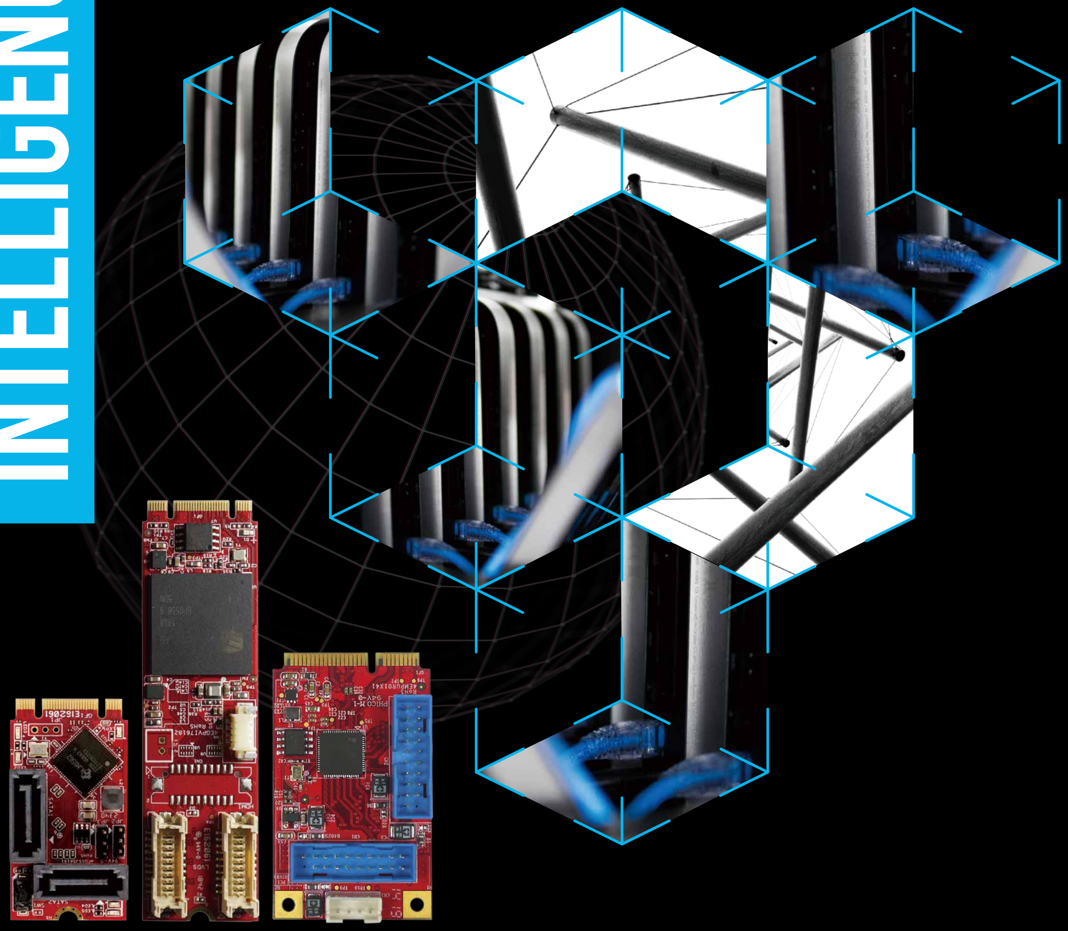
Measurement Index	Operating Range	Resolution	Accuracy (*)	Detection Method	Response Time	Warmup Time
Temperature	-40°C ~ 125°C	0.1°C	±0.5°C	MEMS	30sec	60sec
Humidity	0~100% RH	1% RH	±5%RH	MEMS	30sec	60sec
CO2	0~5,000 ppm	1 ppm	±30 ppm±3% of reading	NDIR	120sec	60sec
PM2.5	0~1000 µg/m3	1 µg/m3	±10 µg/m3±10% of reading	Optical	10sec	300sec
PM10	0~1000 µg/m3	1 µg/m3	±10 µg/m3±10% of reading	Optical	10sec	300sec
TVOC	0~60 ppm	0.01 ppm	±0.1 ppm±10% of reading	MEMS	10sec	300sec
CO	0~1,000 ppm	0.1 ppm	±5 ppm±5% of reading	Electrochemical	30sec	60sec
HCHO	0.01~5 ppm	0.01 ppm	±0.02 ppm±10% of reading	Electrochemical	30sec	300sec
O3	0~5 ppm	0.01 ppm	±0.1 ppm±10% of reading	Electrochemical	60sec	600sec
NO2	0~20 ppm	0.1 ppm	±2% FS	Electrochemical	30sec	600sec
SO2	0~20 ppm	0.1 ppm	±5% FS	Electrochemical	30sec	600sec

(*) Testing conditions at 25°C environment

Sensor Carrier Board

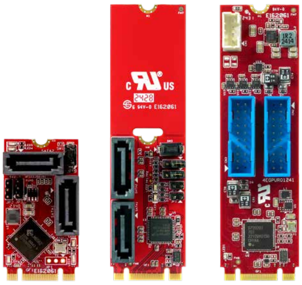
Model	EZU2-I301	
Key Features	USB to I2C Sensor Carrier Board	
Form-Factor	Other	
Input I/F	USB 2.0 Full Speed	
Output I/F	I2C (3.3V)	
Output connector	P2.54mm Pin Header x4 (CN4+CN5, CN6+CN7) P2.0mm Connector x1 (CN2)	
Power Consumption	MAX: 0.695W (3.3V, 139mA)	
Dimension (WxLxH/mm)	50 x 80 x 8.82	
Temperature	Operation: STD: -40°C ~ +85°C Storage: -55°C ~ +95°C	
Order info.	EZU2-I301-W1	
Detection	Temperature	Humidity
Principle	MEMS	MEMS
Measurement range	-40°C ~ +125°C	0 ~ 100% RH
Resolution	0.1°C	1% RH
Accuracy	±0.5°C	±5% RH
Response time(T90) (sec)	<30 sec	<30 sec

EXTENDED INTELLIGENCE



EXTENDED INTELLIGENCE

주변 기기로 상호 연결된 애플리케이션 시나리오를 구축하여 시스템의 기능을 확장합니다 .



Storage & Disk Array

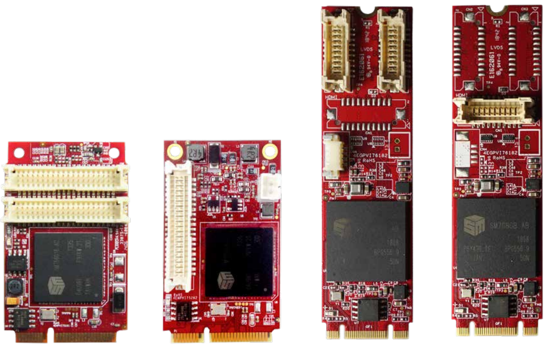
Model	EMPS-3401	EGPS-3401	EMPU-3201	EMPU-3401
Description	mPCIe to four SATA III module	M.2 to four SATA module	mPCIe to dual USB 3.0 Module	mPCIe to four USB 3.0 module
Form Factor	mPCIe	M.2 3042	mPCIe	mPCIe
Input I/F	PCI Express 2.0	PCI Express 2.0 x1	PCI Express 2.0	PCI Express 2.0
Input Connector	mPCIe	M.2 B+M Key	mPCIe	mPCIe
Output I/F	SATA III x4	SATA III x4	USB 3.0 x2	USB 3.0 x4
Output Connector	SATA 7 Pin x 4	SATA 7 Pin x 4	19 Pin box header x 1	19 Pin box header x 2
Dimension (WxLxH/mm)	30 x 50.9 x 10.9	30 x 42 x 10.4	30.0 x 50.9 x 8.45	30.0 x 50.9 x 8.45
Temperature	Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C
Order info.	EMPS-3401-W1	EGPS-3401-C1	EMPU-3201-C1 EMPU-3201-W1	EMPU-3401-C1 EMPU-3401-W1

Model	EGPU-3201	EMPS-32R1	E2SS-32R1	E2SS-32R2
Description	M.2 to dual USB 3.0 Module	mPCIe to dual SATA III RAID module	2.5" SSD to dual mSATA RAID Module	2.5" SSD to dual M.2 RAID Module
Form Factor	M.2 2260/2280	mPCIe	2.5" SSD	2.5" SSD
Input I/F	PCI Express 2.0	PCI Express 2.0	SATA III	SATA III
Input Connector	M.2 B+M Key	mPCIe	SATA 7+15 Pin	SATA 7+15 Pin
Output I/F	USB 3.0 x2	SATA III x2	SATA III x2	SATA III x2
Output Connector	19 Pin box header x 1	SATA 7 Pin x 2	mSATA x 2	M.2 2242/2260/2280 x 2
Dimension (WxLxH/mm)	22.0 x 60.0 x 8.4 22.0 x 80.0 x 8.4	30 x 50.9 x 10.7	69.85 x 100.1 x 11	69.85 x 100.1 x 11
Temperature	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C	STD temp: 0°C ~ 70°C	STD temp: 0°C ~ 70°C
Order info.	EGPU-3201-C1 / EGPU-3201-C2 EGPU-3201-W1/ EGPU-3201-W2	EMPS-32R1-C1	E2SS-32R1-C1	E2SS-32R2-C1

Model	EGSS-32R2	EGPS-32R1	EGPU-3401
Description	M.2 2242/2280 to Dual SATA III RAID Module	M.2 2242/2280 to dual SATA III RAID Module	M.2 to four USB 3.0 Module
Form Factor	M.2 2242/2280	M.2 2242/2280	M.2 2280 B+M Key
Input I/F	SATA III	PCI Express 2.0	PCI Express 2.0
Input Connector	M.2 B+M Key	M.2 B+M Key	M.2 B+M Key
Output I/F	SATA III	SATA III	USB 3.0
Output Connector	SATA 7pin x 2	SATA 7pin x 2	2 x 19 pin header
Dimension (WxLxH/mm)	C1: 22 x 42 x 11 C2: 22 x 80 x 11	22 x 42(80) x 10.85	22 x 80 x 8.45
Temperature	Operation: 0°C ~ 70°C Storage: -55°C ~ 95°C	Operation: 0°C ~ 70°C Storage: -55°C ~ 95°C Controller Tc: 25°C ~ 85°C	STD temp: 0°C ~ 70°C
Order info.	EGSS-32R2-C1 EGSS-32R2-C2	EGPS-32R1-C1 EGPS-32R1-C2	EGPU-3401-C1 EGPU-3401-W1

Testing Tool

Model	EMXX-0101	EMXX-0102
Description	mPCIe to M.2 A-E key module	mPCIe to M.2 B key module
Form Factor	mPCIe	mPCIe
Input I/F	PCI Express , USB 2.0	PCI Express , USB 2.0, SATA
Input Connector	mPCIe	mPCIe
Output I/F	PCI Express , USB 2.0	PCI Express , USB 2.0, SATA
Output Connector	M.2 Key-A-E	M.2 Key B
Dimension (WxLxH/mm)	30 x 54.4 x 8.15	30 x 54.4 x 6.4
Temperature	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C
Order info.	EMXX-0101-W1 (M.2 Key-A) EMXX-0101-W2 (M.2 Key-E)	EMXX-0102-W1



Display

Model	EMPV-1201	EMPV-1202	EGPV-1101
Description	mPCIe to dual VGA and HDMI(DVI) module	mPCIe to VGA and 18/24 bit LVDS module	M.2 to HDMI or DVI and Single/Dual Channel LVDS Module
Form Factor	mPCIe	mPCIe	M.2 2280
Input I/F	PCI Express 1.0	PCI Express 1.0	PCI Express 2.0 x2
Input Connector	mPCIe	mPCIe	M.2 B+M Key
Output I/F	VGA x 2, HDMI x 1(Optional DVI x 1)	VGA, 18/24 bit LVDS	HDMI or DVI-D x 1 , Single & Dual LVDS
Output Connector	40pin 1.25mm x 2 (40DP-1.25)	40pin 1.25mm x 1 (40DP-1.25)	20 pin x 1(HDMI) 20 pin x 2 (LVDS)
Dimension (WxLxH/mm)	31.5 x 50.9 x 8.2	30 x 50.9 x 8.2	22 x 80 x 7.1
Temperature	STD temp: 0°C ~ 70°C	STD temp: 0°C ~ 70°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C
Order info.	EMPV-1201-C1	EMPV-1202-C1 EMPV-1202-C2	EGPV-1101-C1 (HDMI, Standard Temp.) EGPV-1101-W1 (HDMI, Wide Temp.) EGPV-1101-C2 (LVDS, Standard Temp.) EGPV-1101-W2 (LVDS, Wide Temp.) EGPV-1101-C3 (with HDMI Cable, Standard Temp.) EGPV-1101-W3 (with HDMI Cable, Wide Temp.) EGPV-1101-C4 (with DVI Cable, Standard Temp.) EGPV-1101-W4 (with DVI Cable, Wide Temp.)

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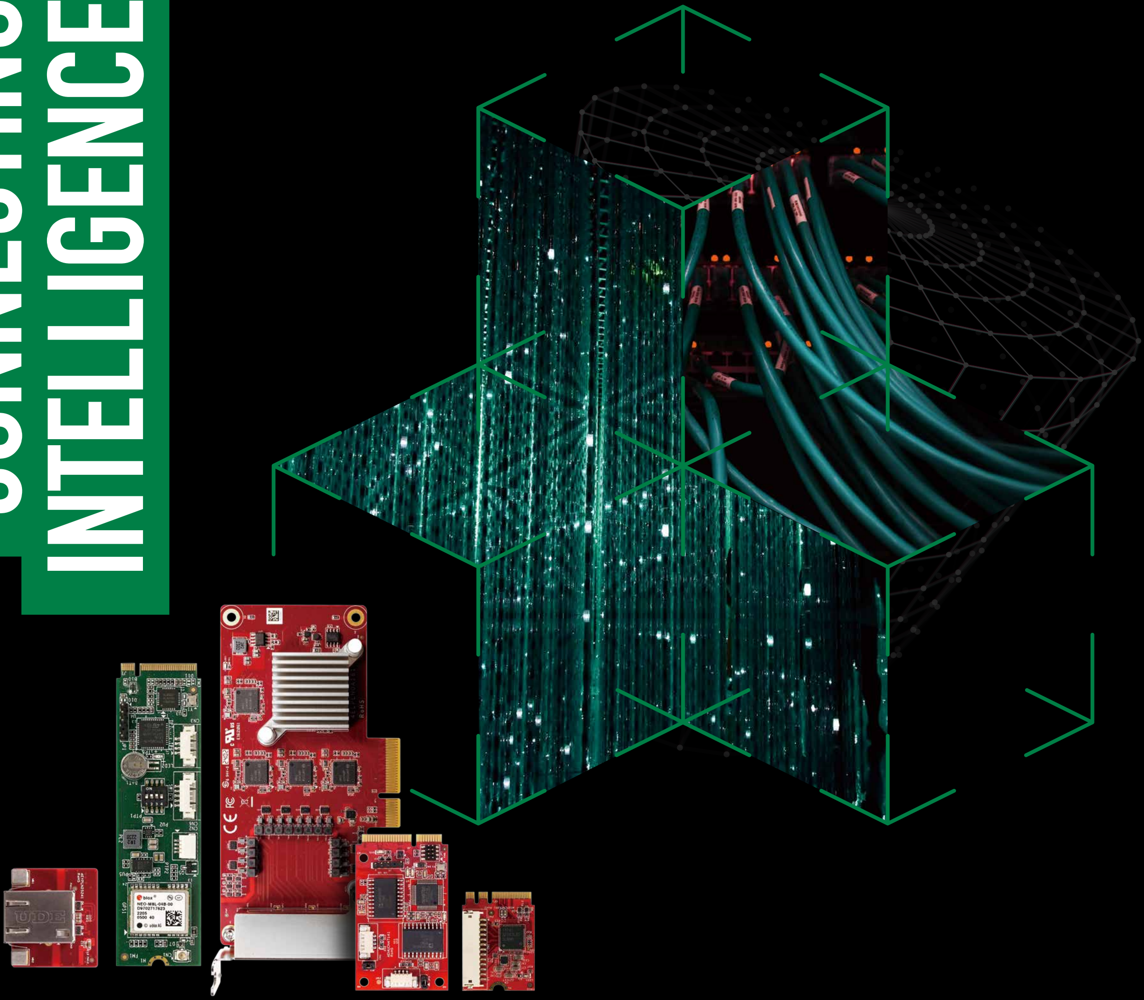
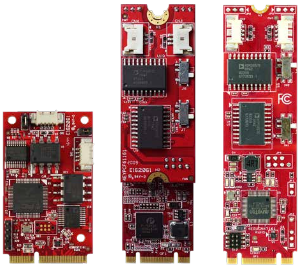
CONNECTING INTELLIGENCE



CONNECTING INTELLIGENCE

실시간 데이터 전송을 위해 원활하게 연결합니다 . 동시 작동을 능숙하게 처리하여 산업 시스템에 안정적인 대역폭을 제공합니다 .



CAN Bus Modules

Model	EMUC-B202	EGPC-B201	EGPC-B4S1	EGPC-B1S1
Description	USB to dual isolated CAN Bus 2.0B/J1939 Module	M.2 to dual isolated CAN Bus 2.0B/ J1939 Module	M.2 to four isolated CAN bus 2.0B Module	M.2 to single isolated CAN bus 2.0B Module
Form Factor	mPCIe	M.2 2260/2280	M.2 2280	M.2 2242
Input I/F	USB 2.0	PCI Express 2.0 x1	PCI Express 1.1 x1	PCI Express 1.1 x1
Input Connector	mPCIe or 5 Pin Header	M.2 B-M	M.2 B+M Key	M.2 B+M Key
Output I/F	CAN Bus 2.0B/J1939 /CANopen x2	CAN Bus 2.0B/J1939 /CANopen x2	CAN Bus 2.0B/J1939 /CANopen x4	CAN Bus 2.0B/J1939 /CANopen x1
Output Connector	DB-9 x 2	DB-9 x 2	DB-9 x 4	DB-9 x 1
Dimension (WxLxH/mm)	30 x 50.9 x 8.35	22 x 60 x 8.05 22 x 80 x 8.05	22 x 80 x 12.9	22 x 42 x 4.8
Temperature	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C
Order info.	EMUC-B202-W1 (CAN 2.0B) EMUC-B202-W2 (J1939) EMUC-B202-W3 (CANopen)	EGPC-B201-W1 (2260, CAN2.0B) EGPC-B201-W2 (2280, CAN2.0B) EGPC-B201-W3 (2260, J1939) EGPC-B201-W4 (2280, J1939) EGPC-B201-W5 (2260, CANopen) EGPC-B201-W6 (2280, CANopen)	EGPC-B4S1-W1 EGPC-B4S1-W2 (J1939, CANopen)	EGPC-B1S1-W1 EGPC-B1S1-W2 (J1939, CANopen)

Model	EGPC-B2S1	EMPC-B2S1	EMUC-B2S3	EMUC-F2S3
Description	M.2 to dual isolated CAN Bus 2.0B/ J1939/CANopen Module	mPCIe to dual isolated CAN Bus 2.0B/J1939/CANopen Module	mPCIe to dual isolated CAN 2.0B/ J1939/CANopen	mPCIe to dual isolated CAN FD
Form Factor	M.2 2280	mPCIe	mPCIe	mPCIe
Input I/F	PCI Express 1.1 x1	PCI Express 1.1 x1	USB 2.0 High Speed (480Mbps)	USB 2.0 High Speed (480Mbps)
Input Connector	M.2 B+M Key	mPCIe	USB 2.0	USB 2.0
Output I/F	CAN Bus 2.0B/J1939 /CANopen x2	CAN Bus 2.0B/J1939 /CANopen x2	CAN Bus 2.0B/J1939 /CANopen x2	CAN FD
Output Connector	DB-9 x 2	DB-9 x 2	DB-9 x 2	DB-9 x 2
Dimension (WxLxH/mm)	22 x 80 x 4.85	30 x 50.9 x 8.25	30 x 50.9 x 8.35	30 x 50.9 x 8.35
Temperature	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C
Order info.	EGPC-B2S1-W1 EGPC-B2S1-W2 (J1939, CANopen)	MPC-B2S1-W1 EMPC-B2S1-W2 (J1939, CANopen)	EMUC-B2S3-W1 EMUC-B2S3-W2 (J1939, CANopen)	EMUC-F2S3-W1

Model	EGUC-F2S3	EGUC-F4S3	ESPC-F2S3	ESPC-F4S3
Description	M.2 2280 to dual isolated CAN FD	M.2 2280 to four isolated CAN FD	PCIe to dual isolated CAN FD	PCIe to dual isolated CAN FD
Form Factor	M.2 2280	M.2 2280	PCIe x 4	PCIe x 4
Input I/F	USB 2.0 High Speed (480Mbps)	USB 2.0 High Speed (480Mbps)	PCI Express 2.0 x1	PCI Express 2.0 x1
Input Connector	M.2 B+M Key	M.2 B+M Key	PCIe x 4	PCIe x 4
Output I/F	CAN FD	CAN FD	CAN FD	CAN FD
Output Connector	DB-9 x 2	DB-9 x 4	DB-9 x 2	DB-9 x 4
Dimension (WxLxH/mm)	22 x 80 x 5.55	22 x 80 x 12.65	111.5 x 110 x 16.79	111.5 x 110 x 16.79
Temperature	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C
Order info.	EGUC-F2S3-W1	EGUC-F4S3-W1	ESPC-F2S3-W1 ESPC-F2S3-W2 (with M.2 slot)	ESPC-F4S3-W1 ESPC-F4S3-W2 (with M.2 slot)

1G LAN

Model	EMPL-G101	EMPL-G201	EMPL-G102	EMPL-G202
Description	mPCIe to single isolated GbE LAN Module	mPCIe to dual isolated GbE LAN mod+C3ule	mPCIe to single isolated GbE LAN horizontal Module	mPCIe to dual isolated GbE LAN horizontal Module
Form Factor	mPCIe	mPCIe	mPCIe	mPCIe
Input I/F	PCI Express 2.1 x1	PCI Express 2.1 x1	PCI Express 2.1 x1	PCI Express 2.1 x1
Input Connector	mPCIe	mPCIe	mPCIe	mPCIe
Output I/F	GbE LAN x 1	GbE LAN x 2	GbE LAN x 1	GbE LAN x 2
Output Connector	RJ45 x 1	RJ45 x 2	RJ45 x 1	RJ45 x 2
Dimension (WxLxH/mm)	30 x 50.9 x 9.2	30 x 50.9 x 9.2	30 x 50.9 x 5.8	30 x 50.9 x 5.8
Temperature	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C
Order info.	EMPL-G101-C3 EMPL-G101-W3 EMPL-G101-C4 (with bracket) EMPL-G101-W4 (with bracket)	EMPL-G201-C3 EMPL-G201-W3 EMPL-G201-C4 (with bracket) EMPL-G201-W4 (with bracket)	EMPL-G102-C3 EMPL-G102-W3 EMPL-G102-C4 (with bracket) EMPL-G102-W4 (with bracket)	EMPL-G202-C3 EMPL-G202-W3 EMPL-G202-C4 (with bracket) EMPL-G202-W4 (with bracket)

Model	EGPL-G101	EGPL-G201	EGPL-G102	EGPL-G202
Description	M.2 to single isolated GbE LAN Module	M.2 to dual isolated GbE LAN Module	M.2 to single isolated GbE LAN Module	M.2 to dual isolated GbE LAN Module
Form Factor	M.2 2280	M.2 2280	M.2 2242	M.2 2242
Input I/F	PCI Express 2.1 x2	PCI Express 2.1 x2	PCI Express 2.1 x2	PCI Express 2.1 x2
Input Connector	M.2 B+M Key	M.2 B+M Key	M.2 B+M Key	M.2 B+M Key
Output I/F	Gbe LAN x 1	Gbe LAN x 2	Gbe LAN x 1	Gbe LAN x 2
Output Connector	RJ45 x 1	RJ45 x 2	RJ45 x 1	RJ45 x 2
Dimension (WxLxH/mm)	22 x 80 x 9.3	22 x 80 x 9.3	22 x 42 x 9.15	22 x 42 x 9.15
Temperature	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C
Order info.	EGPL-G101-C3 EGPL-G101-W3 EGPL-G101-C4 (with bracket) EGPL-G101-W4 (with bracket)	EGPL-G201-C3 EGPL-G201-W3 EGPL-G201-C4 (with bracket) EGPL-G201-W4 (with bracket)	EGPL-G102-C3 EGPL-G102-W3 EGPL-G102-C4 (with bracket) EGPL-G102-W4 (with bracket)	EGPL-G202-C3 EGPL-G202-W3 EGPL-G202-C4 (with bracket) EGPL-G202-W4 (with bracket)

Model	EMPL-G103	EMPL-G203	EGPL-G1N3	EMPL-G2N3
Description	mPCIe to single GbE LAN Module	mPCIe to dual GbE LAN Module	M.2 to single GbE LAN Module	M.2 to dual GbE LAN Module
Form Factor	mPCIe	mPCIe	M.2 2280	M.2 2280
Input I/F	PCI Express 2.1 x1	PCI Express 2.1 x1	PCI Express 2.1 x2	PCI Express 2.1 x1
Input Connector	mPCIe	mPCIe	M.2 B+M Key	M.2 B+M Key
Output I/F	GbE LAN x 1	GbE LAN x 2	GbE LAN x 1	GbE LAN x 2
Output Connector	RJ45 x 1	RJ45 x 2	RJ45 x 1	RJ45 x 2
Dimension (WxLxH/mm)	30 x 50.9 x 9.3	30 x 50.9 x 9.3	22 x 80 x 9	30 x 50.9 x 7.6
Temperature	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C
Order info.	EMPL-G103-C3 EMPL-G103-W3	EMPL-G203-C3 EMPL-G203-W3	EGPL-G1N3-C1 EGPL-G1N3-W1	EGPL-G2N3-C1 EGPL-G2N3-W1

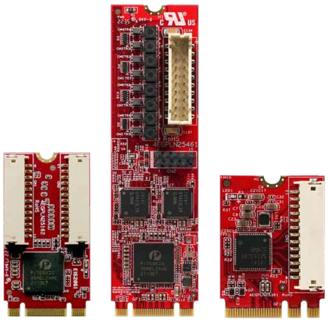
Model	**EMPL-G1S1**	**EMPL-G2S1**	**EMPL-G1S2**
Description	mPCIe to single isolated GbE LAN module	mPCIe to dual isolated GbE LAN module	mPCIe to single isolated GbE LAN horizontal Module
Form Factor	mPCIe	mPCIe	mPCIe
Input I/F	PCI Express 2.1 x1	PCI Express 2.1 x1	PCI Express 2.1 x1
Input Connector	mPCIe	mPCIe	mPCIe
Output I/F	GbE LAN x 1	GbE LAN x 2	GbE LAN x 1
Output Connector	RJ45 x 1	RJ45 x 2	RJ45 x 1
Dimension (WxLxH/mm)	Main Board: 30 x 50.9 x 9.2 Daughter Board: 59.5 x 30 x 17.32	Main Board: 30 x 50.9 x 9.2 Daughter Board: 59.5 x 30 x 17.32	Main board: 30 x 50.95 x 6.15 Daughter board: 59.5 x 30 x 17.4
Temperature	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C
Order info.	EMPL-G1S1-C1 (i225-LM) EMPL-G1S1-W1 (i225-IT) EMPL-G1S1-C2 (i225-LM, with bracket) EMPL-G1S1-W2 (i225-IT, with bracket)	EMPL-G2S1-C1 (i225-LM) EMPL-G2S1-W1 (i225-IT) EMPL-G2S1-C2 (i225-LM, with bracket) EMPL-G2S1-W2 (i225-IT, with bracket)	EMPL-G1S2-C1 (i225-LM) EMPL-G1S2-W1 (i225-IT) EMPL-G1S2-C2 (i225-LM, with bracket) EMPL-G1S2-W2 (i225-IT, with bracket)

Model	**EMPL-G2S2**	**EMPL-G1N1**	**EMPL-G2N1**	**EGPL-G1S1**
Description	mPCIe to dual isolated GbE LAN horizontal Module	mPCIe to single GbE LAN Module	mPCIe to dual GbE LAN Module	M.2 2280 to single isolated GbE LAN Module
Form Factor	mPCIe	mPCIe	mPCIe	M.2 2280
Input I/F	PCI Express 2.1 x 1	PCI Express 2.1 x1	PCI Express 2.1 x1	PCI Express 2.1 x2
Input Connector	mPCIe	mPCIe	mPCIe	M.2 B+M Key
Output I/F	GbE LAN x 2	GbE LAN x 1	GbE LAN x 2	Gbe LAN x 1
Output Connector	RJ45 x 2	RJ45 x 1	RJ45 x 2	RJ45 x 1
Dimension (WxLxH/mm)	Main board: 30 x 50.95 x 6.15 Daughter board: 59.5 x 30 x 17.4	30 x 50.9 x 9.3	30 x 50.9 x 9.3	Main Board: 22 x 80 x 9 Daughter Board: 59.5 x 30 x 17.32
Temperature	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C
Order info.	EMPL-G2S2-C1 (i225-LM) EMPL-G2S2-W1 (i225-IT) EMPL-G2S2-C2 (i225-LM, with bracket) EMPL-G2S2-W2 (i225-IT, with bracket)	EMPL-G1N1-C1 (i225-LM) EMPL-G1N1-W1 (i225-IT)	EMPL-G2N1-C1 (i225-LM) EMPL-G2N1-W1 (i225-IT)	EGPL-G1S1-C1 (i225-LM) EGPL-G1S1-W1 (i225-IT) EGPL-G1S1-C2 (i225-LM, with bracket) EGPL-G1S1-W2 (i225-IT, with bracket)

Model	**EGPL-G2S1**	**EGPL-G1S2**	**EGPL-G2S2**	**EGPL-G1S4**
Description	M.2 2280 to dual isolated GbE LAN Module	M.2 to single isolated GbE LAN Module	M.2 to dual isolated GbE LAN Module	M.2 to single isolated GbE LAN horizontal Module
Form Factor	M.2 2280	M.2 2242	M.2 2242	M.2 2242
Input I/F	PCI Express 2.1 x2	PCI Express 2.1 x2	PCI Express 2.1 x2	PCI Express 2.1 x2
Input Connector	M.2 B+M Key	M.2 B+M Key	M.2 B+M Key	M.2 B+M Key
Output I/F	Gbe LAN x 2	Gbe LAN x 1	Gbe LAN x 2	Gbe LAN x 1
Output Connector	RJ45 x 2	RJ45 x 1	RJ45 x 2	RJ45 x 1
Dimension (WxLxH/mm)	Main Board: 22 x 80 x 9 Daughter Board: 59.5 x 30 x 17.32	Main board: 22 x 42 x 9.01 Daughter board: 50 x 28 x 19.37	Main board: 22 x 42 x 9.01 Daughter board: 50 x 28 x 19.37	Main board: 22 x 42 x 5.95 Daughter board: 50 x 28 x 19.75
Temperature	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C
Order info.	EGPL-G2S1-C1 (i225-LM) EGPL-G2S1-W1 (i225-IT) EGPL-G2S1-C2 (i225-LM, with bracket) EGPL-G2S1-W2 (i225-IT, with bracket)	EGPL-G1S2-C1 (i225-LM) EGPL-G1S2-W1 (i225-IT) EGPL-G1S2-C2 (i225-LM, with bracket) EGPL-G1S2-W2 (i225-IT, with bracket)	EGPL-G2S2-C1 (i225-LM) EGPL-G2S2-W1 (i225-IT) EGPL-G2S2-C2 (i225-LM, with bracket) EGPL-G2S2-W2 (i225-IT, with bracket)	EGPL-G1S4-C1 (i225-LM) EGPL-G1S4-W1 (i225-IT) EGPL-G1S4-C2 (i225-LM, with bracket) EGPL-G1S4-W2 (i225-IT, with bracket)

Model	EGPL-G2S4	EGPL-G1N1	EGPL-G2N1	EGPL-G1S3
Description	M.2 to dual isolated GbE LAN horizontal Module	M.2 to single GbE LAN Module	M.2 to dual GbE LAN Module	M.2 2230 to single isolated GbE LAN module
Form Factor	M.2 2242	M.2 2280	M.2 2280	M.2 2230
Input I/F	PCI Express 2.1 x2	PCI Express 2.1 x2	PCI Express 2.1 x2	PCI Express 2.1 x2
Input Connector	M.2 B+M Key	M.2 B+M Key	M.2 B+M Key	M.2 A+E Key
Output I/F	Gbe LAN x 2	GbE LAN x 1	GbE LAN x 2	GbE LAN x 1
Output Connector	RJ45 x 2	RJ45 x 1	RJ45 x 2	RJ45 x 1
Dimension (WxLxH/mm)	Main board: 22 x 42 x 5.95 Daughter board: 50 x 28 x 19.75	22 x 80 x 9	30 x 50.9 x 7.6	Main board: 22 x 30 x 5.95 Daughter board: 32 x 28 x 19.2
Temperature	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C
Order info.	EGPL-G2S4-C1 (i225-LM) EGPL-G2S4-W1 (i225-IT) EGPL-G2S4-C2 (i225-LM, with bracket) EGPL-G2S4-W2 (i225-IT, with bracket)	EGPL-G1N1-C1 (i225-LM) EGPL-G1N1-W1 (i225-IT)	EGPL-G2N1-C1 (i225-LM) EGPL-G2N1-W1 (i225-IT)	EGPL-G1S3-C1 (i225-LM) EGPL-G1S3-W1 (i225-IT)

Model	ESPL-G401	ELPL-G401	EGPL-G401
Description	PCIe to four GbE LAN Module	PCIe to four isolated GbE LAN Module	M.2 2280 to four isolated GbE LAN Module
Form Factor	Standard PCIe	Low-Profile PCIe	M.2 2280
Input I/F	PCI Express 2.1 x4	PCI Express 2.1 x4	PCI Express 2.1 x2
Input Connector	PCIe x 4	PCIe x 4	M.2 B+M Key
Output I/F	GbE LAN x 4	GbE LAN x 4	GbE LAN x 4
Output Connector	RJ45 x 4	RJ45 x 4	RJ45 x 4
Dimension (WxLxH/mm)	169.55 x 111.15 x 19.6	131.9 x 56.02 x 19.88	Main board: 22 x 80 x 15.3 Daughter board: 41.9 x 64.27 x 21
Temperature	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C
Order info.	ESPL-G401-C1 (i225-LM) ESPL-G401-W1 (i225-IT)	ELPL-G401-C1 (i210-AT) ELPL-G401-W1 (i210-IT)	EGPL-G401-C1 (i350, Mounting hole) EGPL-G401-C2 (i350, PCIe low profile bracket) EGPL-G401-C3 (i350, PCIe standard bracket)



2.5G LAN

Model	EMPL-21S1	EMPL-22S1	EMPL-21S2	EMPL-22S2
Description	mPCIe to single isolated 2.5GbE LAN Module	mPCIe to dual isolated 2.5GbE LAN mod+C3ule	mPCIe to single isolated 2.5GbE LAN horizontal Module	mPCIe to dual isolated 2.5GbE LAN horizontal Module
Form Factor	mPCIe	mPCIe	mPCIe	mPCIe
Input I/F	PCI Express 2.1 x1	PCI Express 2.1 x1	PCI Express 2.1 x1	PCI Express 2.1 x1
Input Connector	mPCIe	mPCIe	mPCIe	mPCIe
Output I/F	2.5GbE LAN x 1	2.5GbE LAN x 2	2.5GbE LAN x 1	2.5GbE LAN x 2
Output Connector	RJ45 x 1	RJ45 x 2	RJ45 x 1	RJ45 x 2
Dimension (WxLxH/mm)	30 x 50.9 x 9.2	30 x 50.9 x 9.2	30 x 50.9 x 5.8	30 x 50.9 x 5.8
Temperature	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C
Order info.	EMPL-21S1-C1 EMPL-21S1-W1 EMPL-21S1-C2 (with bracket) EMPL-21S1-W2 (with bracket)	EMPL-22S1-C1 EMPL-22S1-W1 EMPL-22S1-C2 (with bracket) EMPL-22S1-W2 (with bracket)	EMPL-21S2-C1 EMPL-21S2-W1 EMPL-21S2-C2 (with bracket) EMPL-21S2-W2 (with bracket)	EMPL-22S2-C1 EMPL-22S2-W1 EMPL-22S2-C2 (with bracket) EMPL-22S2-W2 (with bracket)

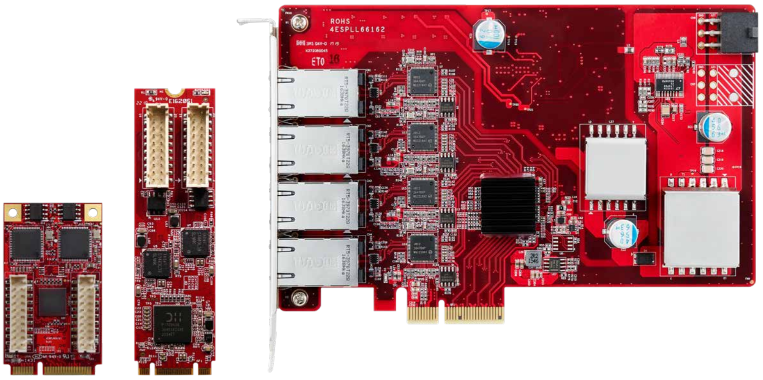
Model	EGPL-21S1	EGPL-22S1	EGPL-21S2	EGPL-22S2
Description	M.2 to single isolated 2.5GbE LAN Module	M.2 to dual isolated 2.5GbE LAN Module	M.2 to single isolated 2.5GbE LAN Module	M.2 to dual isolated 2.5GbE LAN Module
Form Factor	M.2 2280	M.2 2280	M.2 2242	M.2 2242
Input I/F	PCI Express 2.1 x2	PCI Express 2.1 x2	PCI Express 2.1 x2	PCI Express 2.1 x2
Input Connector	M.2 B+M Key	M.2 B+M Key	M.2 B+M Key	M.2 B+M Key
Output I/F	2.5Gbe LAN x 1	2.5Gbe LAN x 2	2.5Gbe LAN x 1	2.5Gbe LAN x 2
Output Connector	RJ45 x 1	RJ45 x 2	RJ45 x 1	RJ45 x 2
Dimension (WxLxH/mm)	22 x 80 x 9.3	22 x 80 x 9.3	22 x 42 x 9.15	22 x 42 x 9.15
Temperature	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C
Order info.	EGPL-21S1-C1 EGPL-21S1-W1 EGPL-21S1-C2 (with bracket) EGPL-21S1-W2 (with bracket)	EGPL-22S1-C1 EGPL-22S1-W1 EGPL-22S1-C2 (with bracket) EGPL-22S1-W2 (with bracket)	EGPL-21S2-C1 EGPL-21S2-W	EGPL-22S2-C1 EGPL-22S2-W1

Model	EGPL-21S4	EGPL-22S4	EMPL-21N1	EMPL-22N1
Description	M.2 to single isolated 2.5GbE LAN horizontal Module	M.2 to dual isolated 2.5GbE LAN horizontal Module	mPCIe to single 2.5GbE LAN Module	mPCIe to dual 2.5GbE LAN Module
Form Factor	M.2 2242	M.2 2242	mPCIe	mPCIe
Input I/F	PCI Express 2.1 x2	PCI Express 2.1 x2	PCI Express 2.1 x1	PCI Express 2.1 x1
Input Connector	M.2 B+M Key	M.2 B+M Key	mPCIe	mPCIe
Output I/F	2.5Gbe LAN x 1	2.5Gbe LAN x 2	2.5GbE LAN x 1	2.5GbE LAN x 2
Output Connector	RJ45 x 1	RJ45 x 2	RJ45 x 1	RJ45 x 2
Dimension (WxLxH/mm)	Main board: 22 x 42 x 5.95 Daughter board: 50 x 28 x 19.75	Main board: 22 x 42 x 5.95 Daughter board: 50 x 28 x 19.75	30 x 50.9 x 9.3	30 x 50.9 x 9.3
Temperature	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C
Order info.	EGPL-21S4-C1 EGPL-21S4-W1	EGPL-22S4-C1 EGPL-22S4-W1	EMPL-21N1-C1 EMPL-21N1-W1	EMPL-22N1-C1 EMPL-22N1-W1

Model	EGPL-21N1	EGPL-22N1	EGPL-21S3	ESPL-2401
Description	M.2 to single 2.5GbE LAN Module	M.2 to dual 2.5GbE LAN Module	M.2 2230 to single isolated 2.5GbE LAN module	PCIe to four 2.5GbE LAN Module
Form Factor	M.2 2280	M.2 2280	M.2 2230	PCIe x4
Input I/F	PCI Express 2.1 x2	PCI Express 2.1 x1	PCI Express 2.1 x2	PCI Express 2.1 x4
Input Connector	M.2 B+M Key	M.2 B+M Key	M.2 A+E Key	PCIe x 4
Output I/F	2.5GbE LAN x 1	2.5GbE LAN x 2	2.5GbE LAN x 1	2.5GbE LAN x 4
Output Connector	RJ45 x 1	RJ45 x 2	RJ45 x 1	RJ45 x 4
Dimension (WxLxH/mm)	22 x 80 x 9	30 x 50.9 x 7.6	Main board: 22 x 30 x 5.95 Daughter board: 32 x 28 x 19.2	169.55 x 111.15 x 19.6
Temperature	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C
Order info.	EGPL-21N1-C1 EGPL-21N1-W1	EGPL-22N1-C1 EGPL-22N1-W1	EGPL-21S3-C1 EGPL-21S3-W1	ESPL-2401-C1 ESPL-2401-W1

10G LAN

Model	EGPL-T102
Description	M.2 2280 to single 10GbE LAN Module
Form Factor	M.2 2280 B+M
Input I/F	PCI Express 3.0 x2
Input Connector	M.2 B+M Key
Output I/F	Single 10 GbE LAN
Output Connector	RJ45 x 1
Dimension (WxLxH/mm)	M.2 Board: 22 x 80 x 14.5 Daughter Board: 31.75 x 28 x 17.7
Temperature	Operation: -20°C ~ 60°C Storage: -55°C ~ 95°C
Order info.	EGPL-T102-C1 EGPL-T102-C2

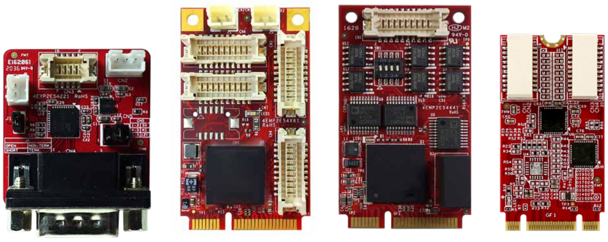


PoE

Model	EMPL-G2P1	EMPL-G2P2	EGPL-G2P1
Description	mPCIe to dual PoE Module	mPCIe to dual PoE+ Module	M.2 to dual PoE Module
Form Factor	mPCIe	mPCIe	M.2 2280
Input I/F	PCI Express 2.1	PCI Express 2.1	PCI Express 2.1 x1
Input Connector	mPCIe	mPCIe	M.2 B+M Key
Output I/F	PoE x 2	PoE+ x 2	PoE x 2
Output Connector	RJ45 x 2	RJ45 x 2	RJ45 x 2
Dimension (WxLxH/mm)	Main Board: 30 x 50.9 x 9.2 Daughter Board: 58.2 x 72.7 x 23.8	Main Board: 30 x 50.9 x 9.2 Daughter Board: 58.2 x 72.7 x 23.8	Main Board: 30 x 50.9 x 9.2 Daughter Board: 58.2 x 72.7 x 23.8
Temperature	STD temp: 0° ~ 70°C Wide temp: -40° ~ 85°C	STD temp: 0° ~ 70°C Wide temp: -40° ~ 85°C	STD temp: 0° ~ 70°C Wide temp: -40° ~ 85°C
Order info.	EMPL-G2P1-C5 (Mounting hole, 4pin header) EMPL-G2P1-W5 (Mounting hole, 4pin header) EMPL-G2P1-C6 (Bracket, 4pin header) EMPL-G2P1-W6 (Bracket, 4pin header) EMPL-G2P1-C7 (Mounting hole, DC Jack) EMPL-G2P1-W7 (Mounting hole, DC Jack) EMPL-G2P1-C8 (Bracket, DC Jack) EMPL-G2P1-W8 (Bracket, DC Jack)	EMPL-G2P2-C3 (Mounting hole, 4pin header) EMPL-G2P2-W3 (Mounting hole, 4pin header) EMPL-G2P2-C4 (Bracket, 4pin header) EMPL-G2P2-W4 (Bracket, 4pin header)	EGPL-G2P1-C5 (Mounting hole, 4pin header) EGPL-G2P1-W5 (Mounting hole, 4pin header) EGPL-G2P1-C6 (Bracket, 4pin heade) EGPL-G2P1-W6 (Bracket, 4pin header) EGPL-G2P1-C7 (Mounting hole) EGPL-G2P1-W7 (Mounting hole, DC Jack) EGPL-G2P1-C8 (Bracket, DC Jack) EGPL-G2P1-W8 (Bracket, DC Jack)

Model	ESPL-G4P1	EMPL-G2P3	EMPL-G2P4
Description	PCIe to four PoE/PoE+ Module	mPCIe to dual PoE Module	mPCIe to dual PoE+ Module
Form Factor	Standard PCIe	mPCIe	mPCIe
Input I/F	PCI Express 2.1 x4	PCI Express 2.1	PCI Express 2.1
Input Connector	PCIe x 4	mPCIe	mPCIe
Output I/F	PoE/PoE+ x 4	PoE x 2	PoE+ x 2
Output Connector	RJ45 x 4	RJ45 x 2	RJ45 x 2
Dimension (WxLxH/mm)	169.55 x 111.15 x 19.6	Main Board: 30 x 50.9 x 9.2 Daughter Board: 72.7 x 56.3 x 22.07	Main Board: 30 x 50.9 x 9.2 Daughter Board: 72.7 x 56.3 x 22.07
Temperature	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C
Order info.	ESPL-G4P1-C1 ESPL-G4P1-W1	EMPL-G2P3-C1 (Mounting hole, 4pin header) EMPL-G2P3-W1 (Mounting hole, 4pin header) EMPL-G2P3-C2 (Bracket, 4pin header) EMPL-G2P3-W2(Bracket, 4pin header) EMPL-G2P3-C3 (Mounting hole, DC Jack) EMPL-G2P3-W3 (Mounting hole, DC Jack) EMPL-G2P3-C4 (Bracket, DC Jack) EMPL-G2P3-W4(Bracket, DC Jack)	EMPL-G2P4-C1 (Mounting hole, 4pin header) EMPL-G2P4-W1 (Mounting hole, 4pin header) EMPL-G2P4-C2 (Bracket, 4pin header) EMPL-G2P4-W2(Bracket, 4pin header)

Model	EGPL-G2P3	EGPL-G2P4	ESPL-G4P3
Description	M.2 to dual PoE Module	M.2 to dual PoE Module	PCIe to four PoE/PoE+ Module
Form Factor	M.2 2280	M.2 2280	Standard PCIe
Input I/F	PCI Express 2.1 x1	PCI Express 2.1 x1	PCI Express 2.1 x4
Input Connector	M.2 B+M Key	M.2 B+M Key	PCIe x 4
Output I/F	PoE x 2	PoE+ x 2	PoE/PoE+ x 4
Output Connector	RJ45 x 2	RJ45 x 2	RJ45 x 4
Dimension (WxLxH/mm)	Main Board: 22 x 80 x 9 Daughter Board: 72.7 x 58.2 x 23.8	Main Board: 22 x 80 x 9 Daughter Board: 72.7 x 58.2 x 23.8	169.55 x 111.15 x 19.6
Temperature	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C	STD temp: 0°C ~ 70°C Wide temp: -40°C ~ 85°C
Order info.	EGPL-G2P3-C1 (Mounting hole, 4pin header) EGPL-G2P3-W1 (Mounting hole, 4pin heade) EGPL-G2P3-C2 (Bracket, 4pin heade) EGPL-G2P3-W2 (Bracket, 4pin header) EGPL-G2P3-C3 (Mounting hole) EGPL-G2P3-W3 (Mounting hole, DC Jack) EGPL-G2P3-C4 (Bracket, DC Jack) EGPL-G2P3-W4 (Bracket, DC Jack)	EGPL-G2P4-C1 (Mounting hole, 4pin header) EGPL-G2P4-W1 (Mounting hole, 4pin header) EGPL-G2P4-C2 (Bracket, 4pin header) EGPL-G2P4-W2 (Bracket, 4pin header)	ESPL-G4P3-C1 ESPL-G4P3-W1



Serial

Model	EMP2-X202	EMP2-X402	EMP2-X203	EMP2-X403	EMP2-X404
Description	mPCIe to dual RS-422/485 Module	mPCIe to four RS-422/485 Module	mPCIe to dual RS-232 Module	mPCIe to four RS-232 Module	mPCIe to four RS-232/422/485 Module
Form Factor	mPCIe	mPCIe	mPCIe	mPCIe	mPCIe
Input I/F	PCI Express 2.0	PCI Express 2.0	PCI Express 2.0	PCI Express 2.0	PCI Express 2.0
Input Connector	mPCIe	mPCIe	mPCIe	mPCIe	mPCIe
Output I/F	RS-422/485 x 2	RS-422/485 x 4	RS-232 x 2	RS-232 x 4	RS-232/422/485 x 4
Output Connector	DB-9 x 2	DB-9 x 4	DB-9 x 2	DB-9 x 4	DB-9 x 4
Dimension (WxLxH/mm)	30 x 50.9 x 8.2	30 x 50.9 x 8.2	30 x 50.9 x 6.7	30 x 50.9 x 6.7	30 x 50.9 x 6.1
Temperature	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C
Order info.	EMP2-X202-W1	EMP2-X402-W1	EMP2-X203-W1	EMP2-X403-W1	EMP2-X404-W1

Model	EMP2-X801	EMP2-X2S1	EMP2-X4S1	EMP2-X4S2	EGP2-X401
Description	mPCIe to eight RS-232/422/485 Module	mPCIe to two Isolated RS-232 Module	mPCIe to four Isolated RS-485 Module	mPCIe to dual Isolated RS-422 & RS-485 Module	M.2 to four RS-232/422/485 Module
Form Factor	mPCIe	mPCIe	mPCIe	mPCIe	M.2 2242
Input I/F	PCI Express 2.0	PCI Express 2.0	PCI Express 2.0	PCI Express 2.0	PCI Express 2.0 x1
Input Connector	mPCIe	mPCIe	mPCIe	mPCIe	M.2 B+M Key
Output I/F	RS-232/422/485 x 8	RS-232 x 2	RS-485 x 4	RS-422 x 2, RS-485 x 2	RS-232/422/485 x 4
Output Connector	DB-9 x 8	DB-9 x 2	DB-9 x 4	DB-9 x 4	DB-9 x 4
Dimension (WxLxH/mm)	30 x 50.9 x 6.1	30 x 50.9 x 12.9	30 x 50.9 x 12.55	30 x 50.9 x 12.55	Vertical: 22 x 42 x 6.45 Horizontal: 22 x 42 x 7.65
Temperature	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C
Order info.	EMP2-X801-W1	EMP2-X2S1-W1	EMP2-X4S1-W1	EMP2-X4S2-W1	EGP2-x401-W1 (Vertical connector) EGP2-x401-W2 (Horizontal connector)

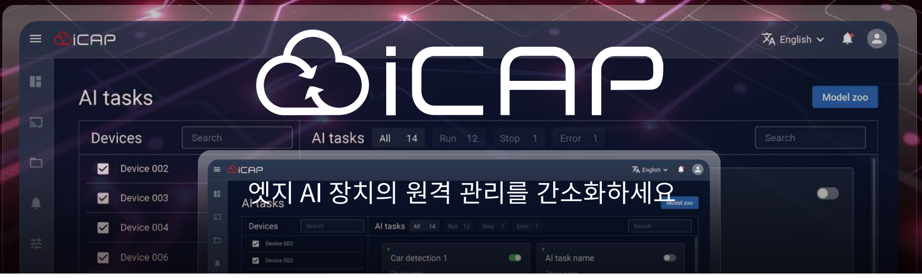
Model	EGP2-X203	EGP2-X403	EGP2-X4S1
Description	M.2 to dual RS-232 Module	M.2 to four RS-232 Module	M.2 to four isolated RS-422 & RS-485 Module
Form Factor	M.2 2242	M.2 2242	M.2 2280
Input I/F	PCI Express 1.1	PCI Express 1.1	PCI Express 2.0 x1
Input Connector	M.2 B+M Key	M.2 B+M Key	M.2 B+M Key
Output I/F	RS-232 x 2	RS-232 x 4	RS-422 x 4 or RS-485 x 4
Output Connector	DB-9 x 2	DB-9 x 4	DB-9 x 4
Dimension (WxLxH/mm)	Vertical: 22 x 42 x 6.83 Horizontal: 22 x 42 x 7.93	Vertical: 22 x 42 x 6.83 Horizontal: 22 x 42 x 7.93	Vertical: 22 x 80 x 6.83 Horizontal: 22 x 80 x 7.93
Temperature	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C	Wide temp: -40°C ~ 85°C
Order info.	EGP2-X203-W1 (Vertical connector) EGP2-X203-W2 (Horizontal connector)	EGP2-X403-W1 (Vertical connector) EGP2-X403-W2 (Horizontal connector)	EGP2-X4S1-W1 (Vertical connector) EGP2-X4S1-W2 (Horizontal connector)

MANAGEMENT INTELLIGENCE

MANAGEMENT INTELLIGENCE

우리의 고급 소프트웨어와 서비스를 통해 실제 애플리케이션에서 손쉽게 관리할 수 있어 , 모든 단계에서 최적의 성능을 보장합니다 .

iCAP 클라우드 관리 플랫폼



엣지 AI 장치의 원격 관리를 간소화하세요

iCAP, 이노디스크 클라우드 관리 플랫폼,은 원격 장치 및 AI 모델 관리를 간소화합니다. 모든 브라우저를 통해 접근할 수 있으며, 시스템 건강 상태를 실시간으로 모니터링하고, 저장 수명에 대한 맞춤형 알림을 제공합니다.

iCAP은 또한 원활한 AI 모델 배포를 지원하며, 효율적이고 사용자 친화적인 클라우드 관리 솔루션을 제공합니다.

Reboot / Recover Edge Device

Notification Data Collection

Monitor and Manage Platform

Notification

iCAP 장점

WINDOWS
LINUX
ANDROID APP

다양한 호환성

iCAP 에이전트는 Windows와 Linux 플랫폼 모두와 호환되며, 다양한 웹 브라우저를 통해 원활하게 접근할 수 있습니다. 또한, 모바일 앱을 지원하여 사용자가 원격으로 장치를 모니터링하고 제어할 수 있으며, 아웃오브밴드(OOB) 재부팅 기능도 제공합니다.

효율적인 이벤트 추적기

이벤트 알림 추적기는 모든 변경 사항을 기록하고 사용자에게 실시간으로 정보를 제공하여 발생할 수 있는 문제를 신속하게 해결할 수 있도록 지원합니다.

무선(OTA) 업데이트

이 기능은 BIOS, 저장 장치 펌웨어 및 이미지 업그레이드를 지원하며, 관리되는 엣지 장치나 미리 정의된 그룹에 업데이트 파일을 손쉽게 배포할 수 있습니다.

원스톱 AI 모델 학습, 관리 및 배포

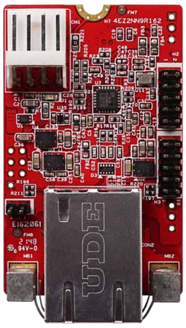
iVIT를 통합하여 모델 라이브러리를 제공하고, 학습된 AI 모델을 플랫폼을 통해 엣지 장치에 손쉽게 배포할 수 있습니다.

원격 재해 복구

iCAP은 인밴드 및 아웃오브밴드 관리를 완벽하게 지원하며, 원키 복구 기능을 통해 장애가 발생한 장치를 신속하게 정상 상태로 복구합니다.

스토리지/DRAM 모니터링

iCAP은 스토리지/DRAM 모니터링을 지원하여 사용자가 iSMART 스토리지/DRAM 정보와 모듈 예측을 원격으로 확인할 수 있도록 제공합니다.



OOB

Model	InnoAgent EZ2N-0XL1
Description	Out-of-Band Remote Management Module
Network I/F	10/100 Mbps LAN (RJ45)
Network Protocol	MQTT
Host I/F	3.3V UART, RS232 (Pitch 2.0mm Pin Header)
Remote Control I/O	3.3V GPIO x 6 (2 GPIO can be I2C) Power SW x2 (Pitch 2.0mm Pin Header)
Power Source	+5V Standby Power Input (4pin floppy male connector)
Dimensions(W*L*H/mm)	51 x 31.3 x 19.05
Temperature	-40°C ~ 85°C
Order info.	EZ2N-0XL1-W1 (Private Cloud: SDK, iCAP 2.0) EZ2N-0XL1-W3 (Private Cloud: with Standard Bracket) EZ2N-0XL1-W4 (Private Cloud: with Low-profile Bracket)

MACHINE-LEARNING INTELLIGENCE

MACHINE-LEARNING INTELLIGENCE

AI 학습 및 추론 기능으로 데이터 인사이트의 잠재력을 최대한 활용합니다 .

iVIT

비전 인텔리전스 툴킷

누구나 간단하게 사용할 수 있는 노코드 AI

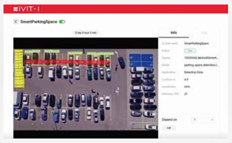
iVIT, 인노디스크 비전 인텔리전스 툴킷은 AI 모델 학습과 추론을 높은 효율로 간소화합니다. 주요 딥러닝 프레임워크를 통합하여 개발자가 제품 프로토타입을 빠르게 제작하고 맞춤형 AI 모델을 구축할 수 있도록 지원합니다.

코드 불필요

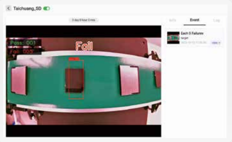
AI 모델 배포

카메라 스트리밍

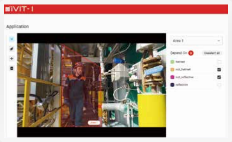
이벤트 로깅



스마트 교통



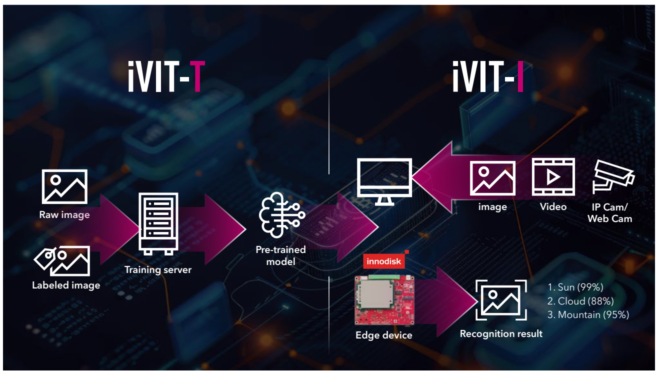
스마트 팩토리



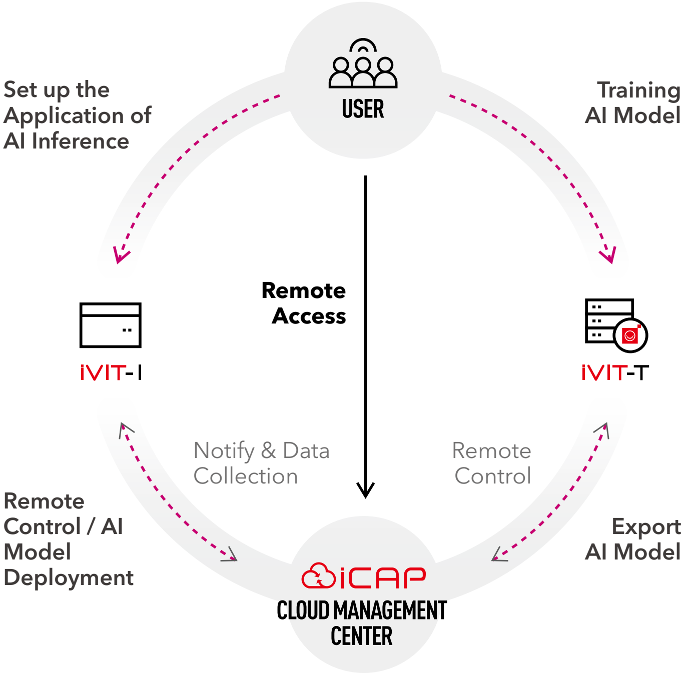
스마트 감시

맞춤형 솔루션을 위한 AI 개발 조화

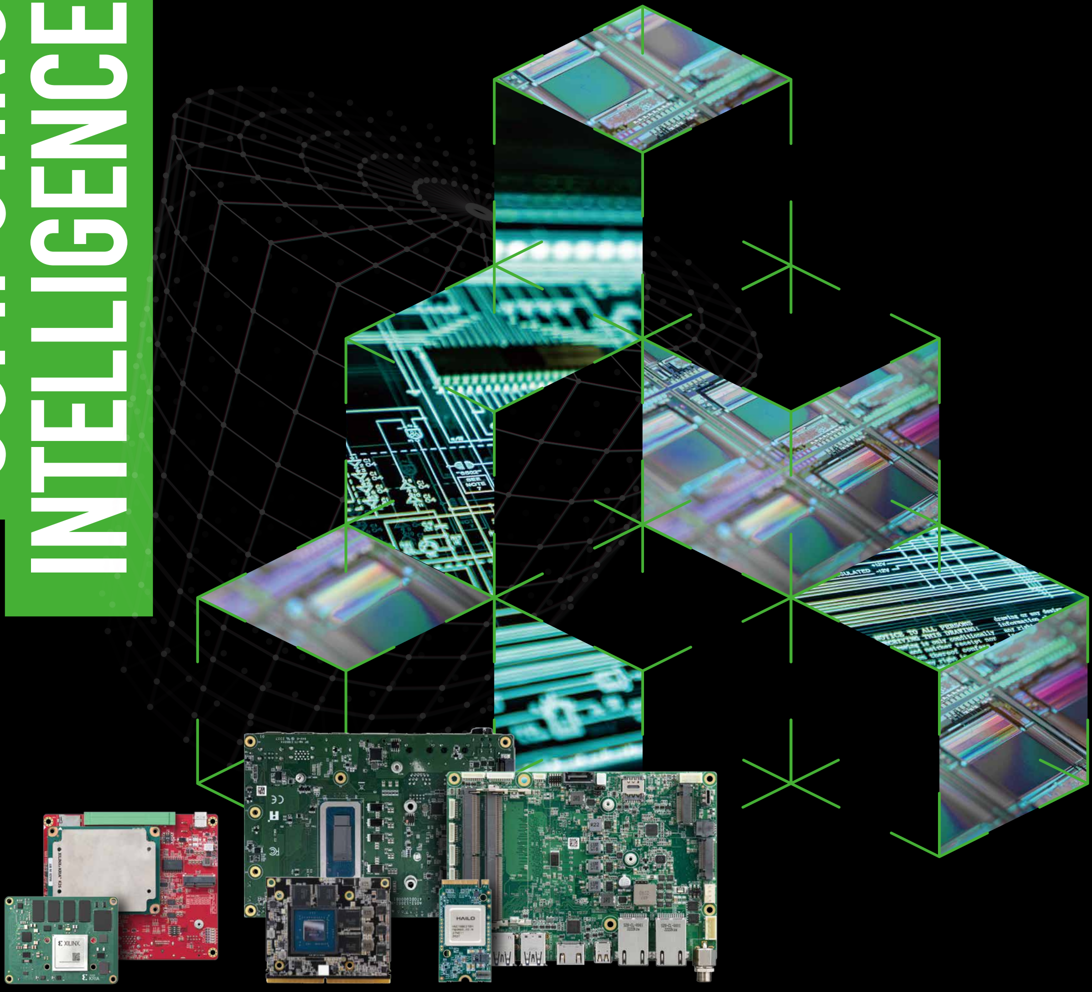
iVIT 솔루션은 AI 모델 학습을 위한 iVIT-T와 모델 추론을 위한 iVIT-I를 포함합니다. 이 두 가지를 함께 사용하면 머신 비전 애플리케이션의 정확한 요구 사항에 맞게 AI 모델을 원활하게 맞춤화할 수 있습니다.



iVIT와 iCAP 시너지를 통한 AI 잠재력 발휘



COMPUTING INTELLIGENCE



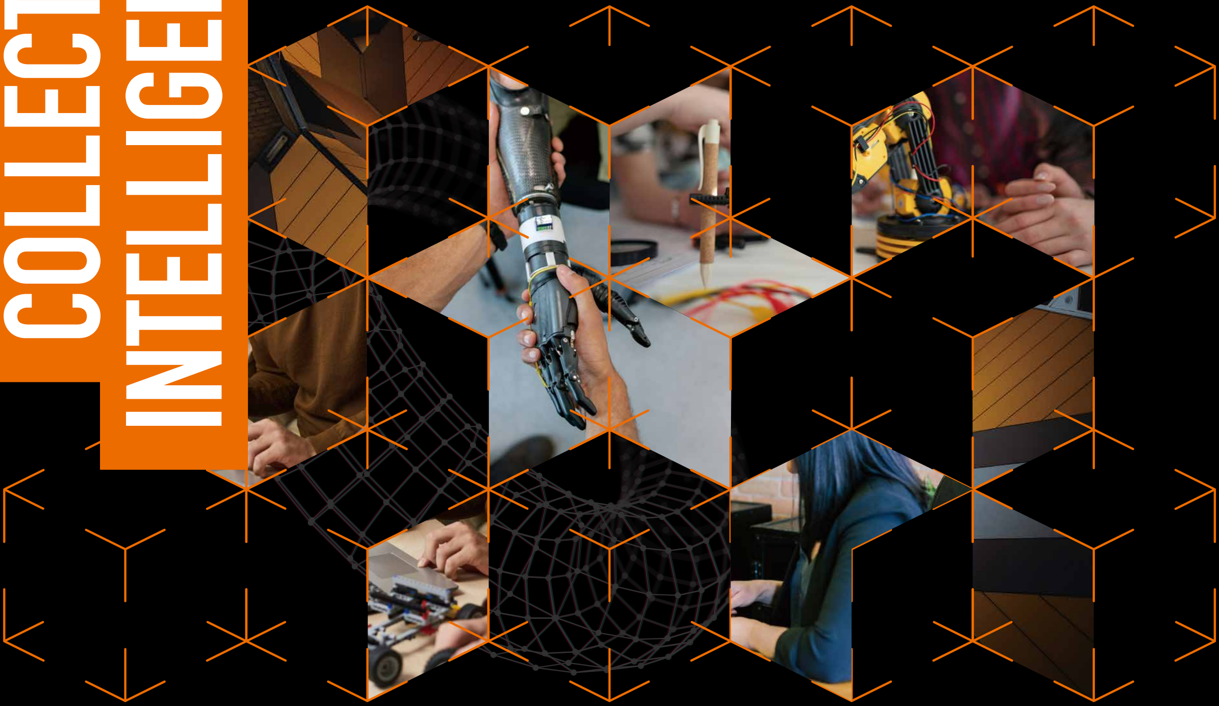
COMPUTING INTELLIGENCE

AI 가속 컴퓨팅 시스템으로 엣지에서 데이터 처리 및 분석을 혁신합니다 .

FPGA

Module Name	EXMU-X261	EXOU-X261
Module Type	FPGA Machine Vision Solution Kit	FPGA Machine Vision Solution Box
Form Factor	SOM and Carrier Board	SOM and Carrier Board
Controller	Kria K26 SOM	Kria K26 SOM
AI Computing power	1.4 TOPS	1.4 TOPS
Memory	4GB LPDDR4 on SOM	4GB LPDDR4 on SOM
Storage	16GB eMMC on SOM ; Micro SD ; NVME SSD (M.2 2242 M-Key PCIe Gen 3 x2)	16GB eMMC on SOM ; Micro SD ; NVME SSD (M.2 2242 M-Key PCIe Gen 3 x2)
Dimensions (WxLxH/mm)	120 x 100 x 30.37 (with K26)	142 x 104 x 70
Display Interface	1 x HDMI 1.4	1 x HDMI 1.4
Ethernet	1 x RJ45 GbE LAN	1 x RJ45 GbE LAN
I/O	4 x USB 3.1 Gen 1	4 x USB 3.1 Gen 1
	1 x 15pin terminal block (GPIO x 5, UART x 1, CAN Bus x 2, I2C x 1)	1 x 15pin terminal block (GPIO x 5, UART x 1, CAN Bus x 2, I2C x 1)
	1 x MicroSD	1 x MicroSD
	1 x USB Type-C (Debug Only)	1 x USB Type-C (Debug Only)
	1 x Power Button	1 x Power Button
	1 x Reset Button	1 x Reset Button
Expansion	M.2 2230 E-Key (PCIe Gen 2 x1, USB 2.0)	M.2 2230 E-Key (PCIe Gen 2 x1, USB 2.0)
	M.2 2242 M-Key (PCIe Gen 3 x4)	M.2 2242 M-Key (PCIe Gen 3 x4)
Power Requirement	12V +/-5% DC Power supply	12V +/-5% DC Power supply
Power Consumption	Approximately 17.64W (12V, 1.47A)	Approximately 17.64W (12V, 1.47A)
Temperature	Operation : S/T 0°C ~ 70°C (Ta) W/T -40°C ~ 85°C (Ta)	Operation : S/T 0°C ~ 70°C (Ta) W/T -40°C ~ 85°C (Ta)
	Storage : -55°C ~ 95°C (Ta)	Storage : -55°C ~ 95°C (Ta)
Storage Humidity	5% to 95%, non-condensing	5% to 95%, non-condensing
OS Support	Linux (Kernel 5.15.19)	Linux (Kernel 5.15.19)
Certification	CE / FCC class A	CE / FCC class A
Vibration	3G, IEC 60068-2-64, random vibration, 5 ~ 500Hz, 1hr/axis	3G, IEC 60068-2-64, random vibration, 5 ~ 500Hz, 1hr/axis
Shock	30G, IEC 60068-2-27, half sine, 11ms duration	30G, IEC 60068-2-27, half sine, 11ms duration
Warranty	3 Years	3 Years

COLLECTIVE INTELLIGENCE



COLLECTIVE INTELLIGENCE

업계 리더들과 협력하여 지능형 생태계를 구축하고 엣지 AI 애플리케이션의 무한한 가능성을 열어드립니다 .

또한 , 우리는 공급업체 , 글로벌 고객 , 직원들과 협력하여 환경 문제를 해결하고 사회적 책임을 다하며 긍정적인 영향을 추구합니다 .

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